

FIBs

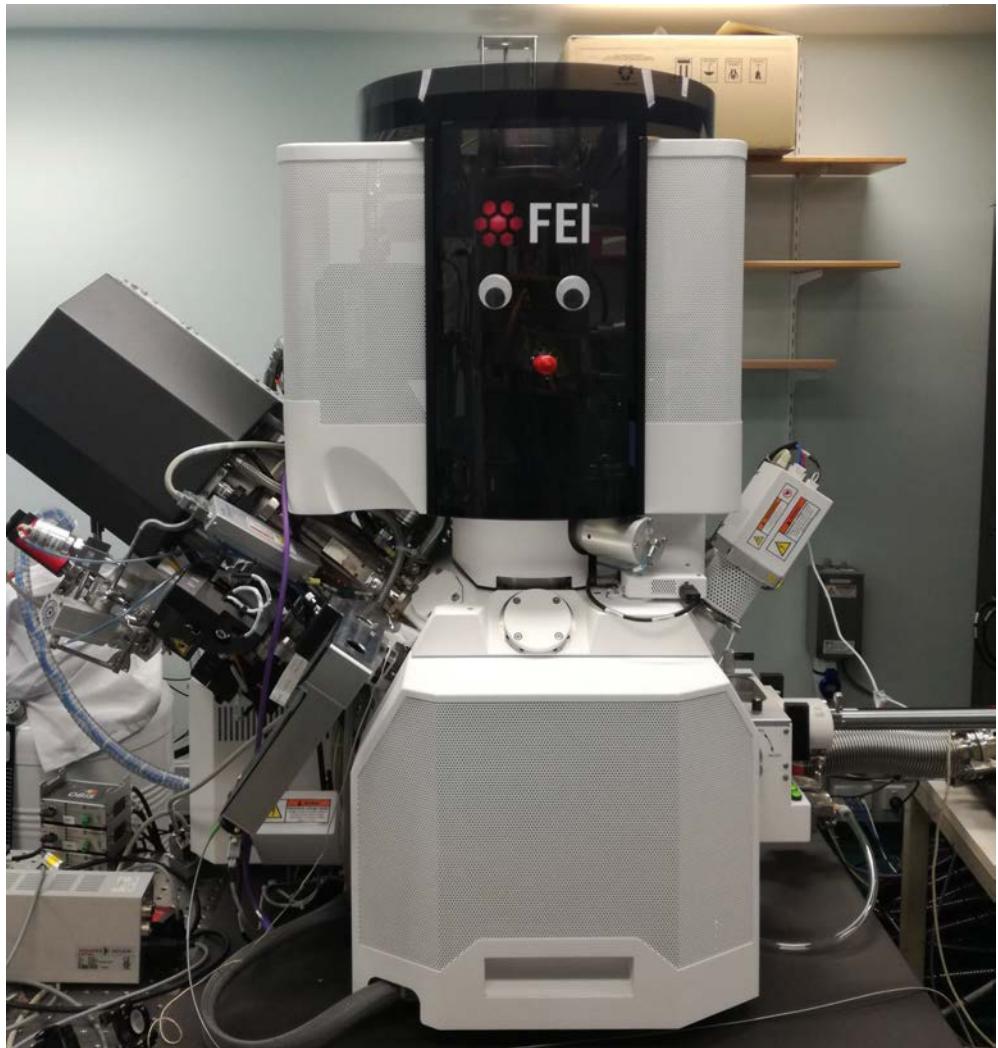
Alex de Marco

Tuesday, April 1, 2025

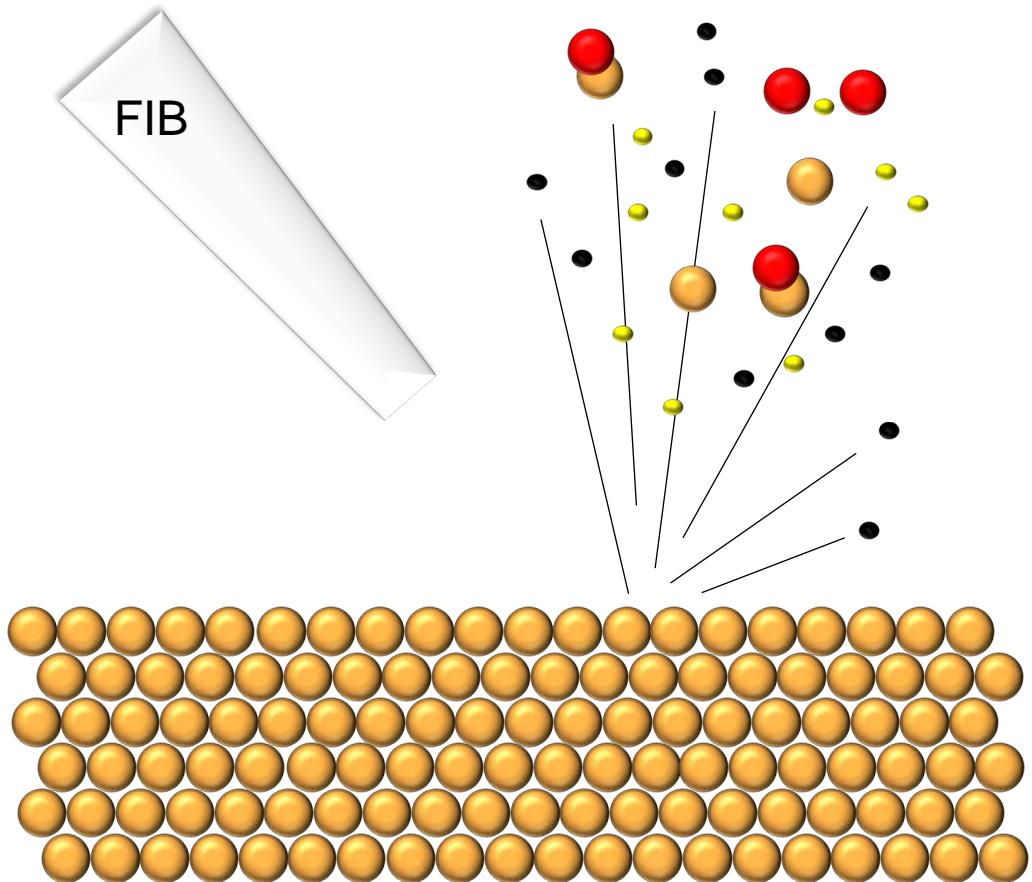


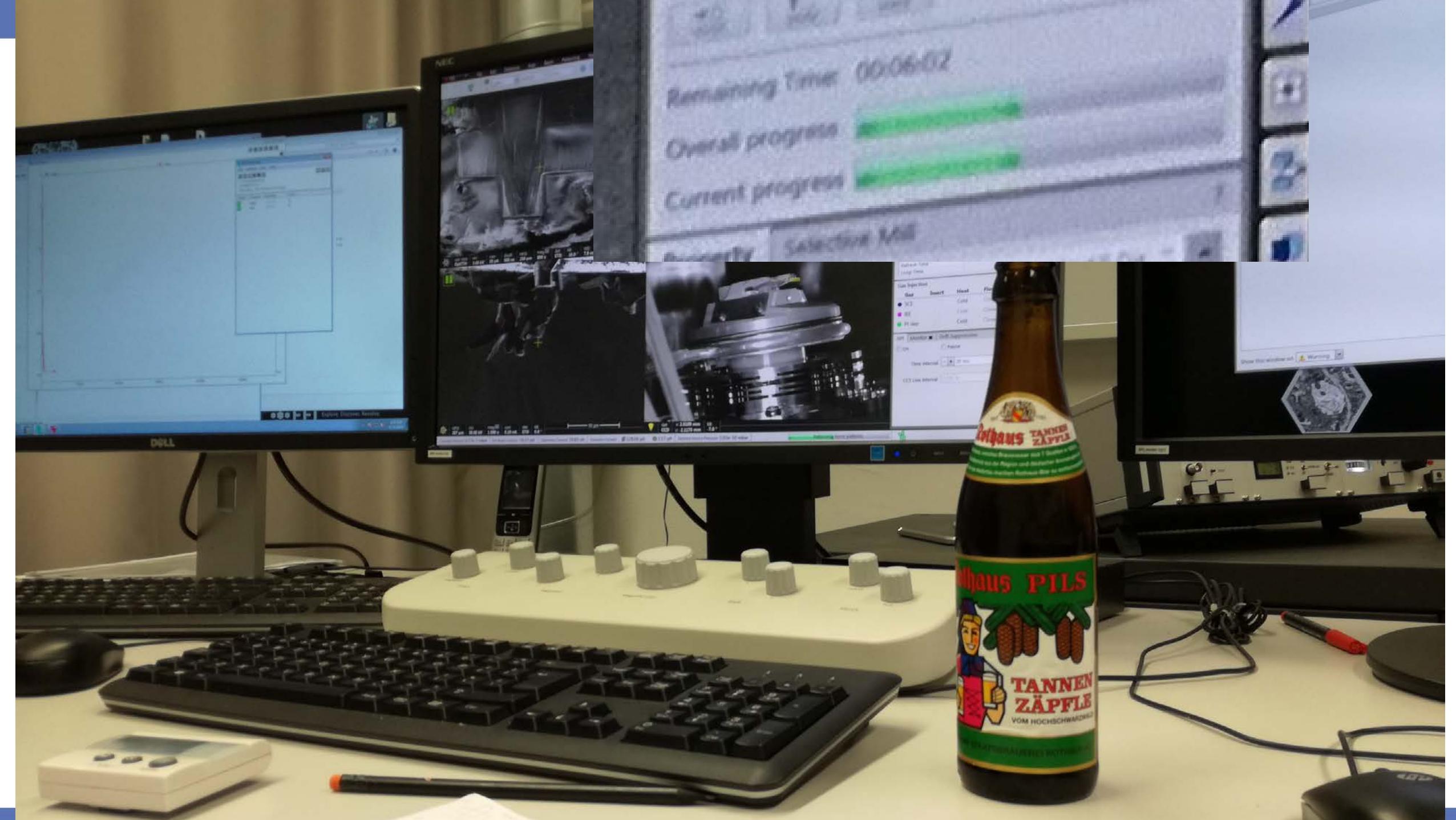
NYSBC SEMC

Focused ion beam microscopy



- Beam ion
- Photon
- Sample atom
- Electron

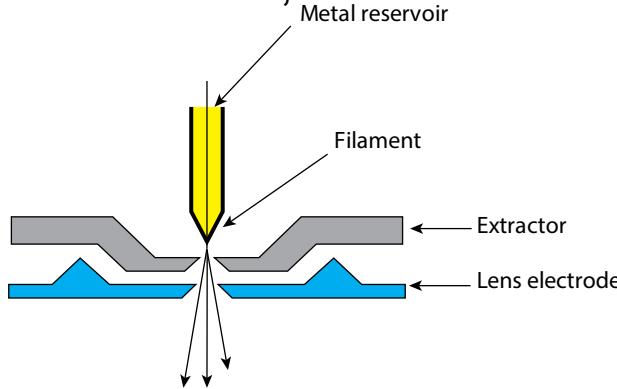




Plasma focused ion beam microscopy

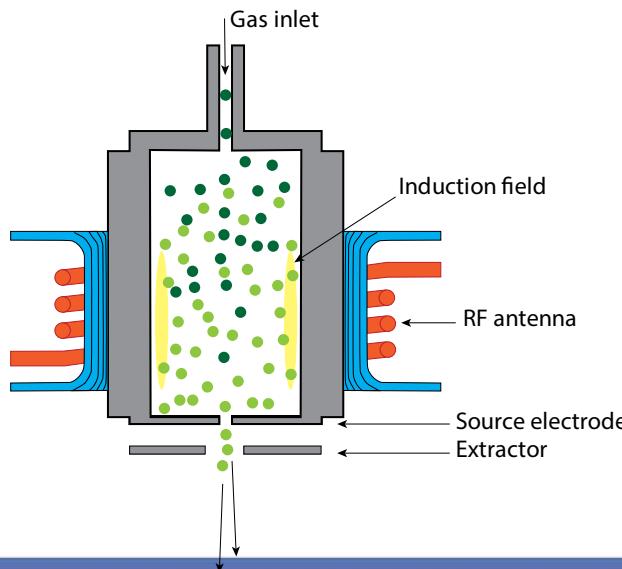
LMIS: 1pA to 1e5 pA

Sources: Ga, Au/Si



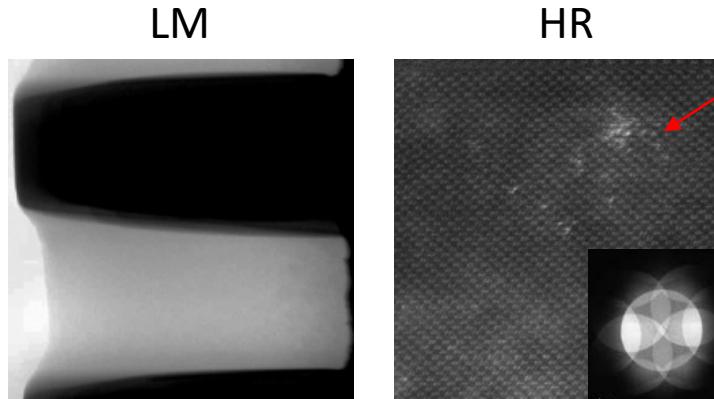
Plasma: 1pA to 2.5e6 pA

Sources: He, Ne, Ar, Kr, Xe, O, N

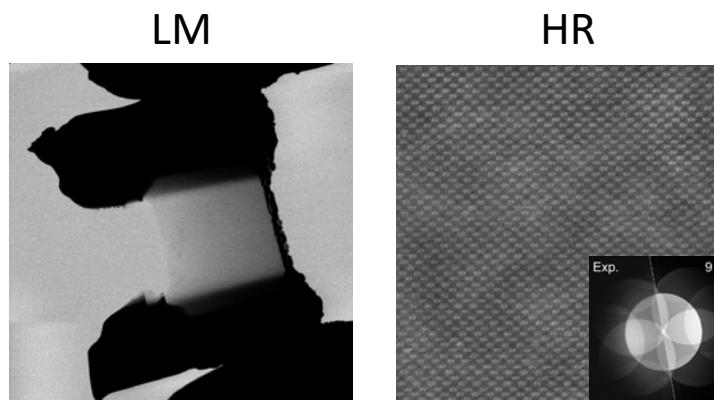


TEM sample preparation on C-diamond

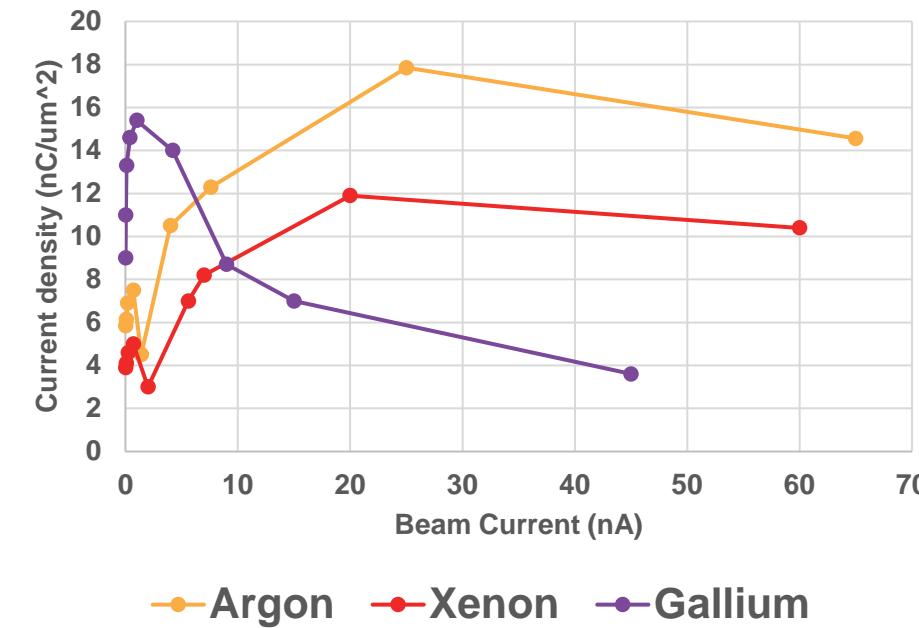
Ga



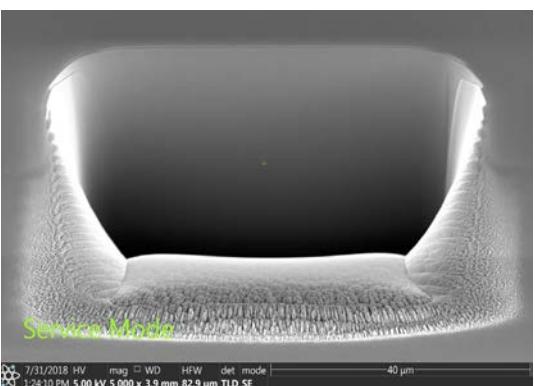
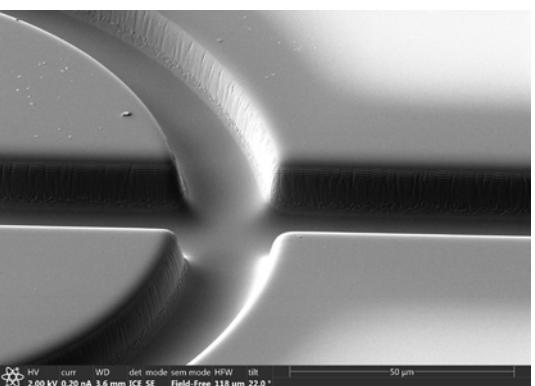
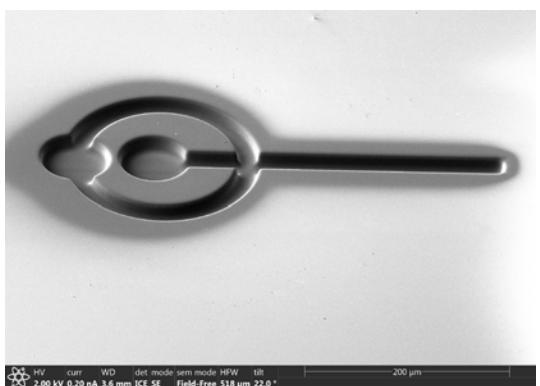
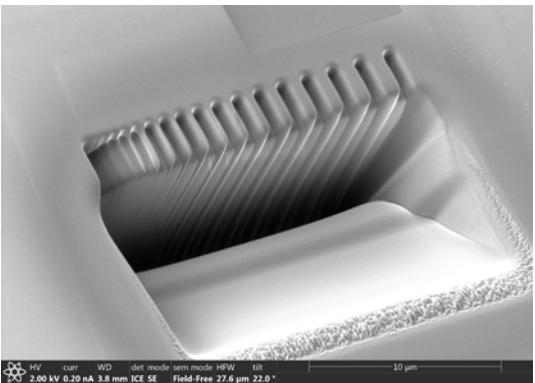
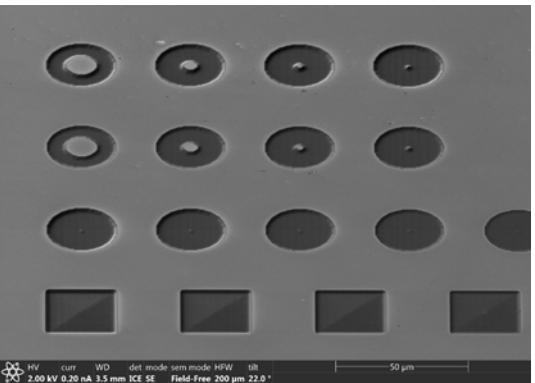
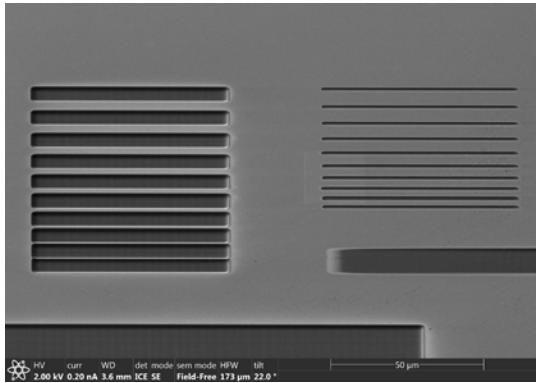
O₂



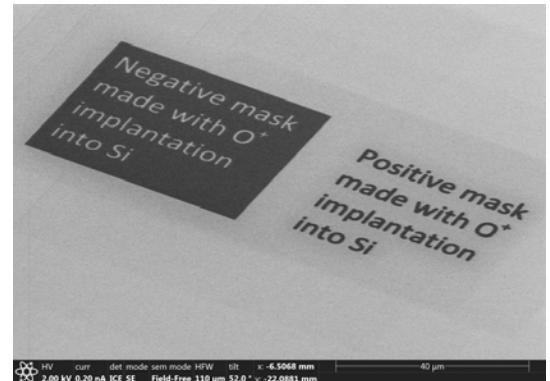
Metal implantation



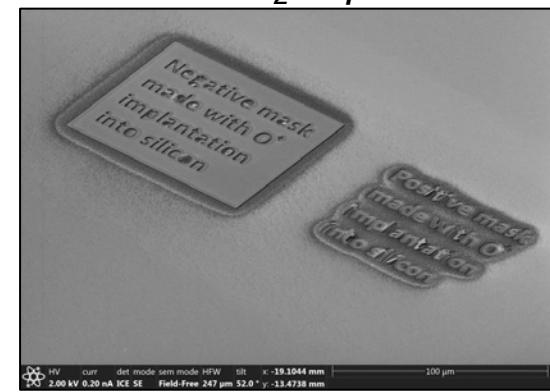
FIB uses



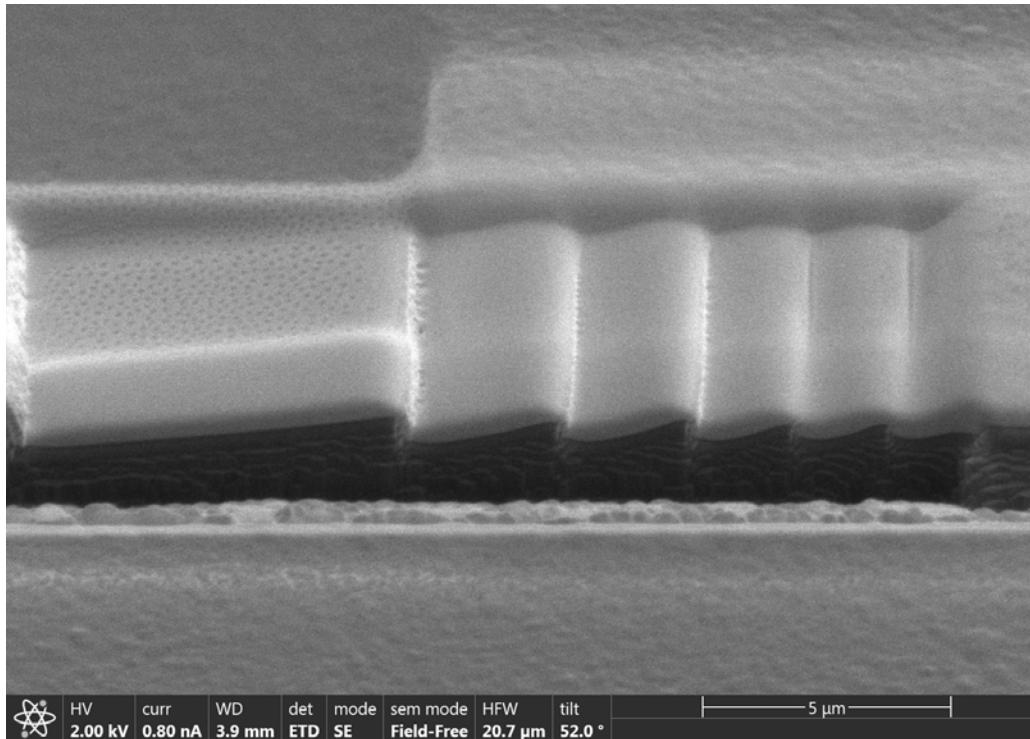
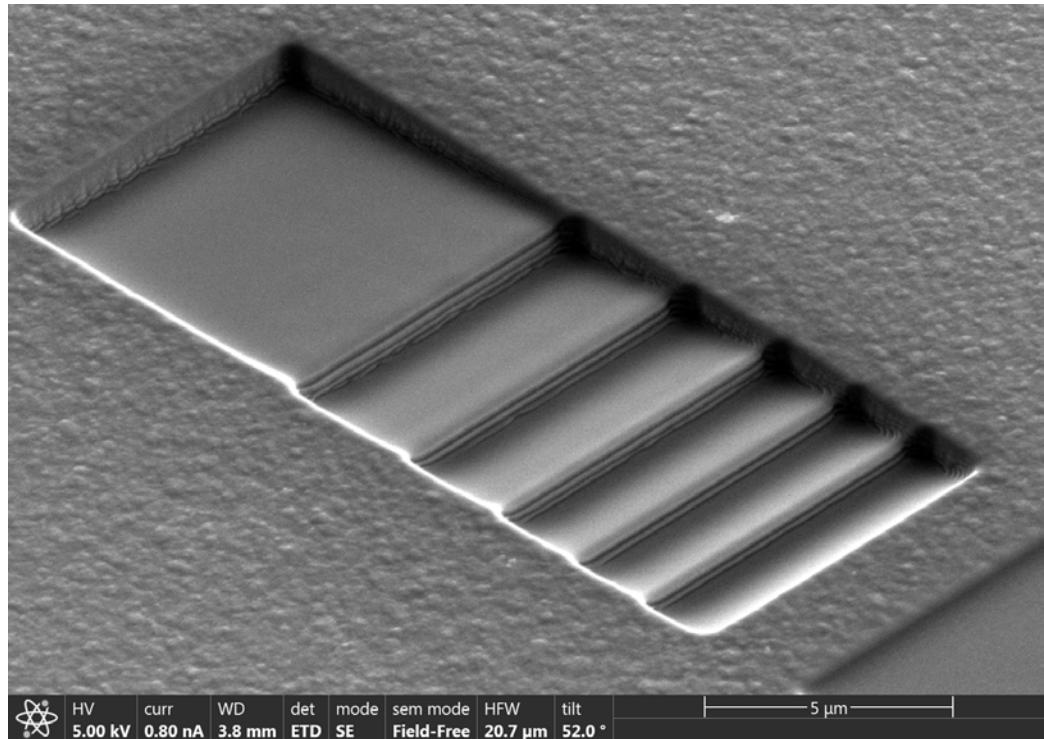
Direct mask writing
Si substrate irradiated with O⁺



After XeF₂ exposure

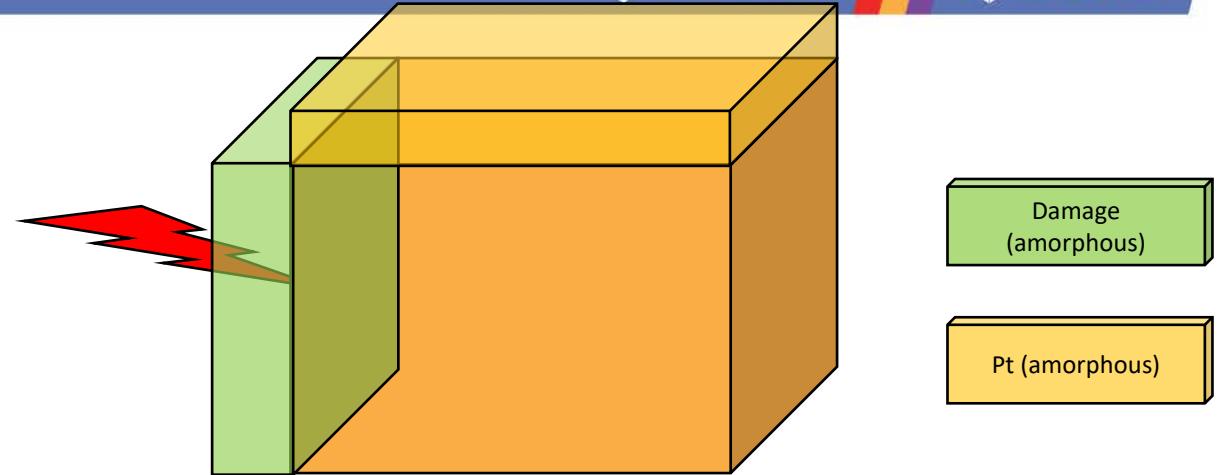


Ion dose can be tuned

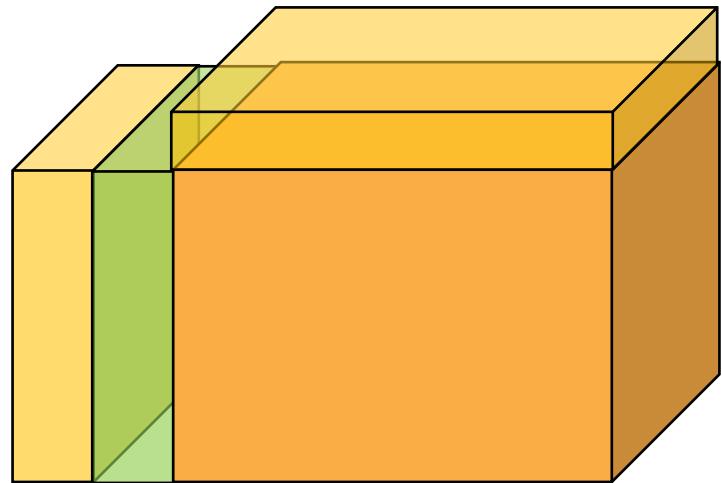




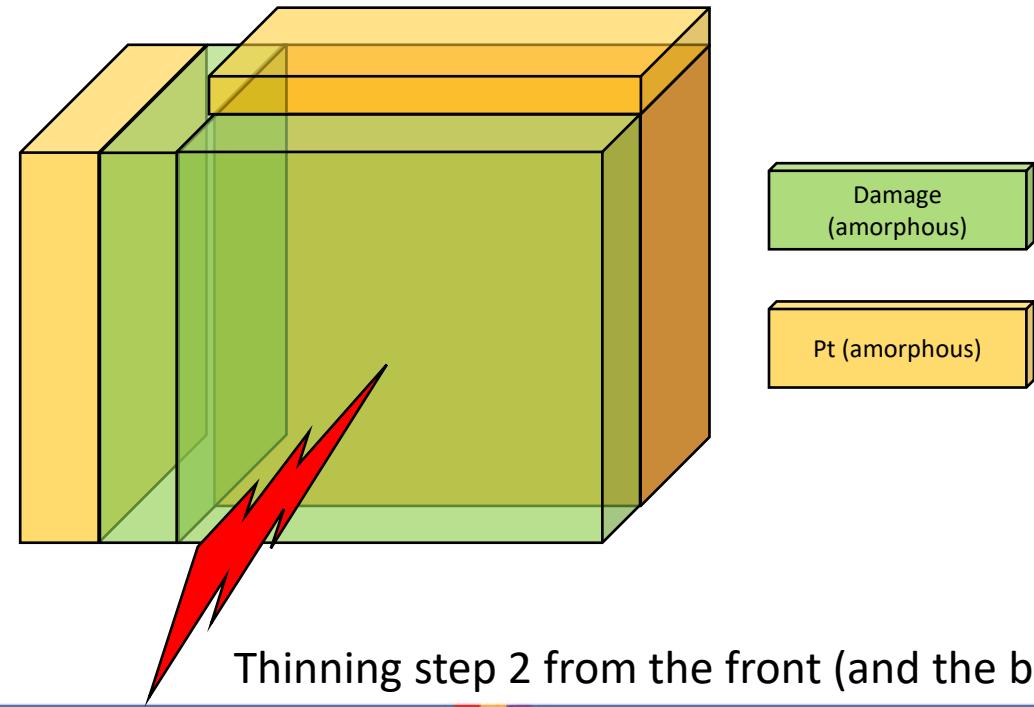
Original state



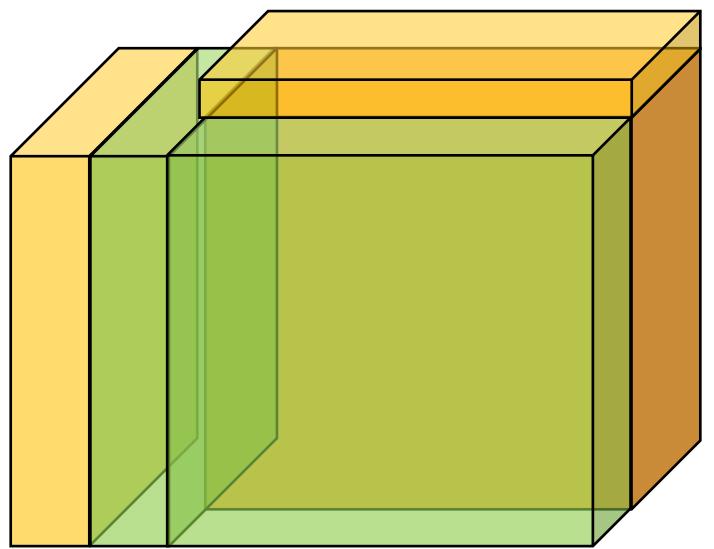
Thinning step 1 from the side



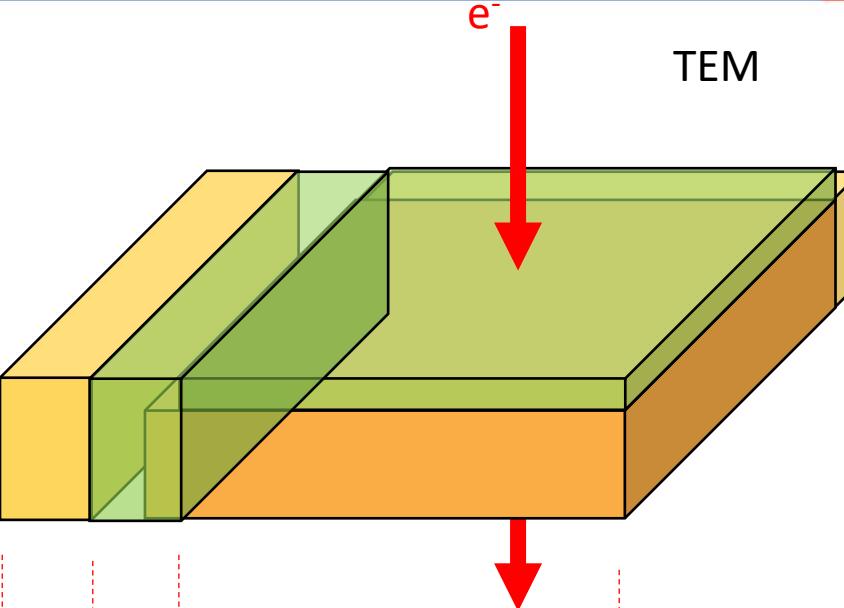
Add Pt cap on the side



Thinning step 2 from the front (and the back)



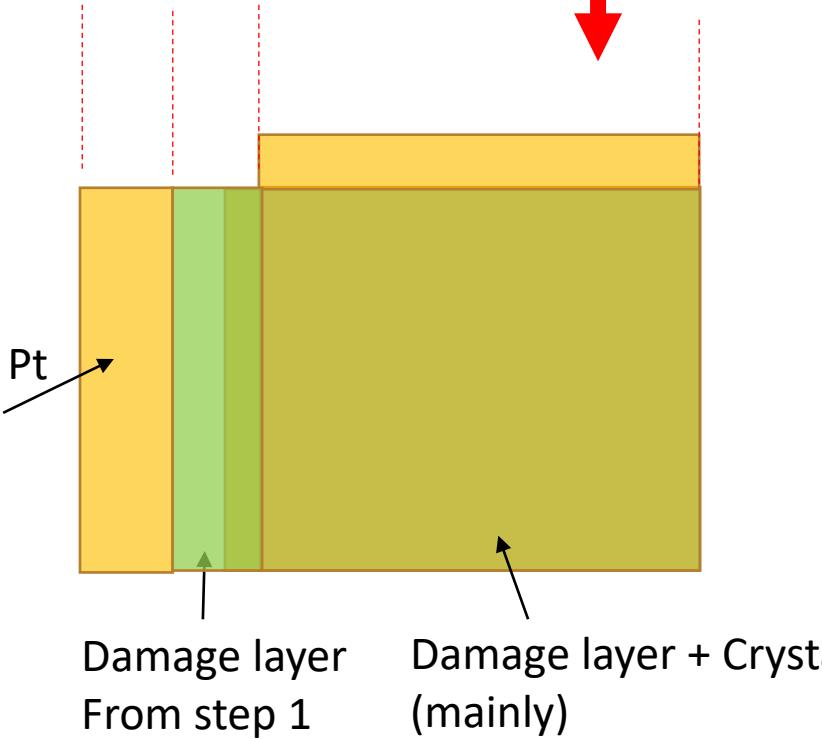
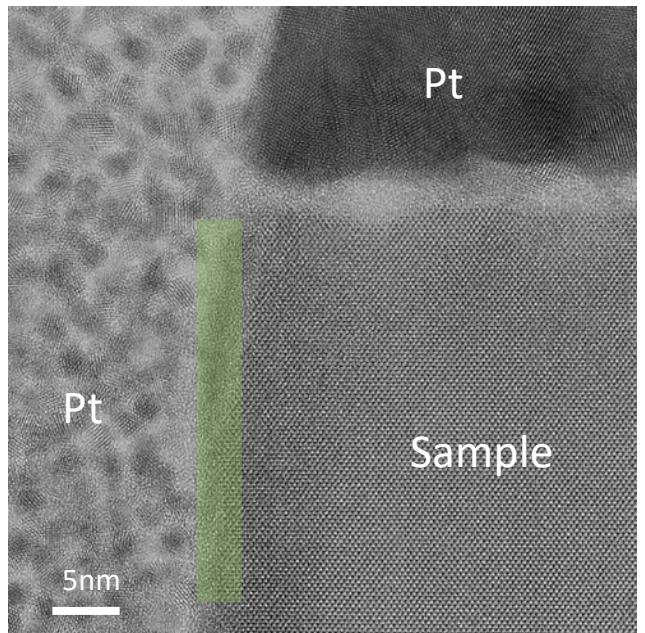
Flip the sample



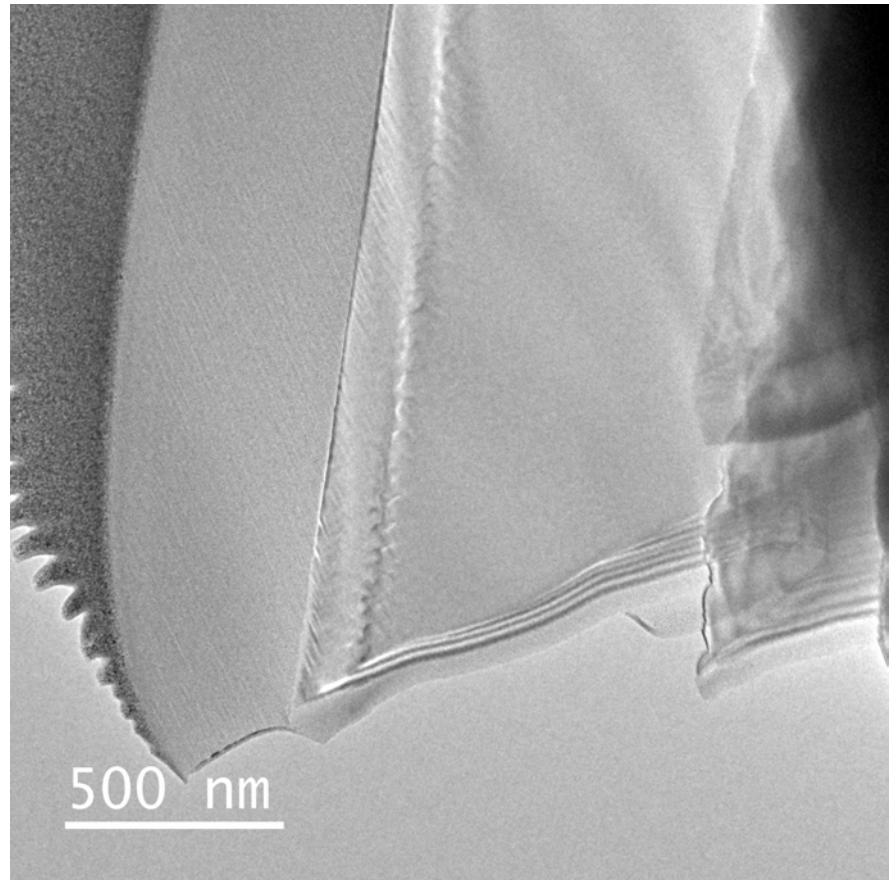
TEM

Damage
(amorphous)

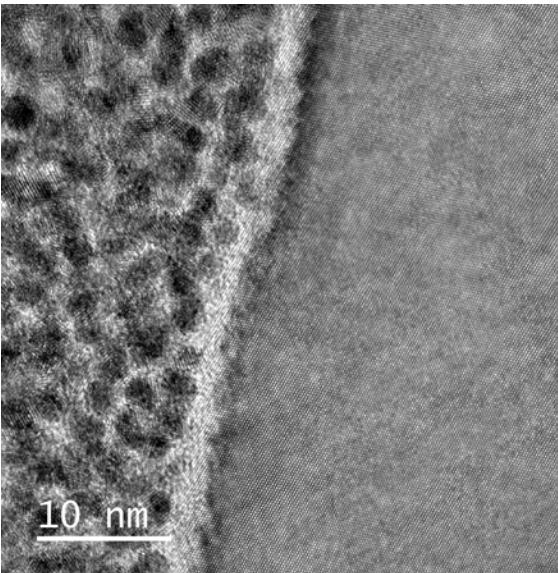
Pt (amorphous)



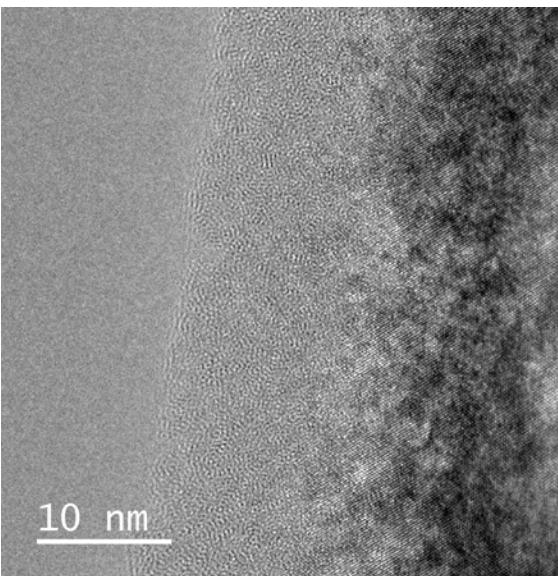
Damage on Diamond



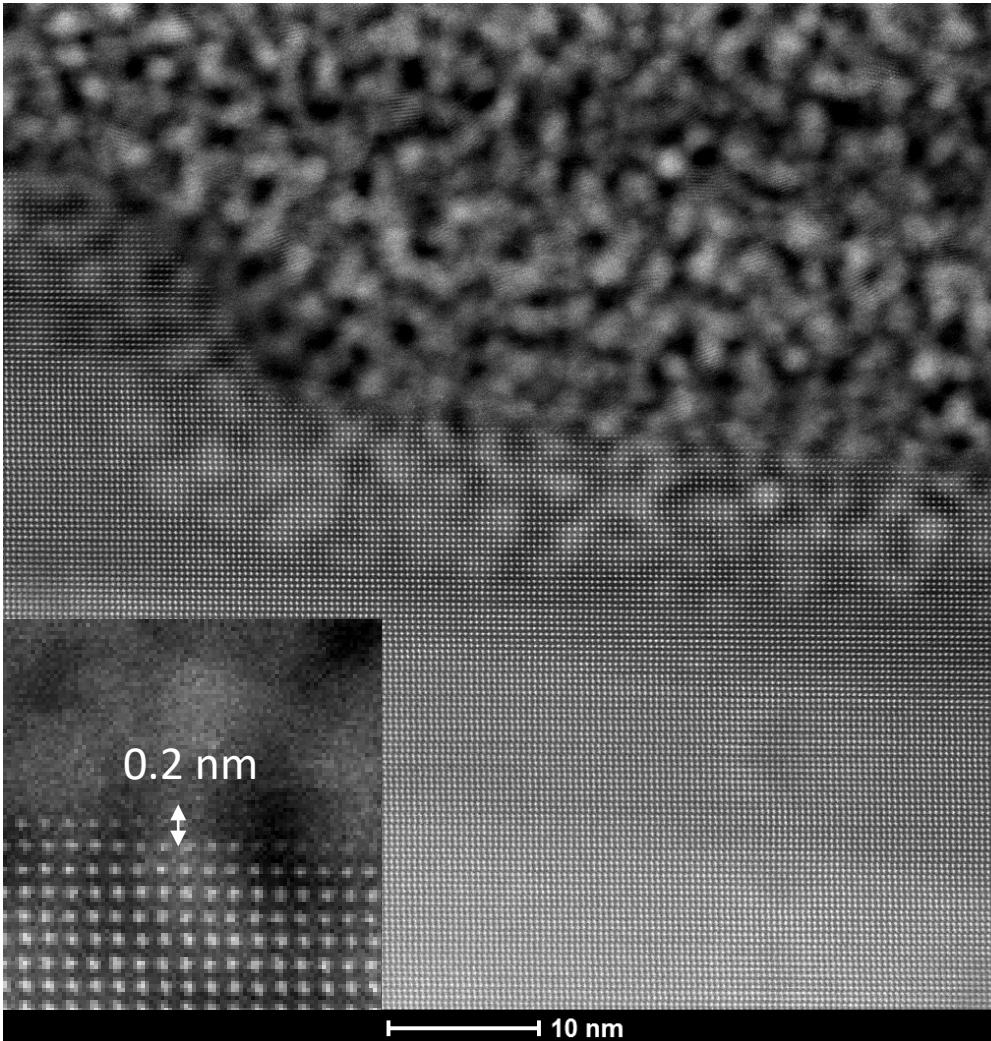
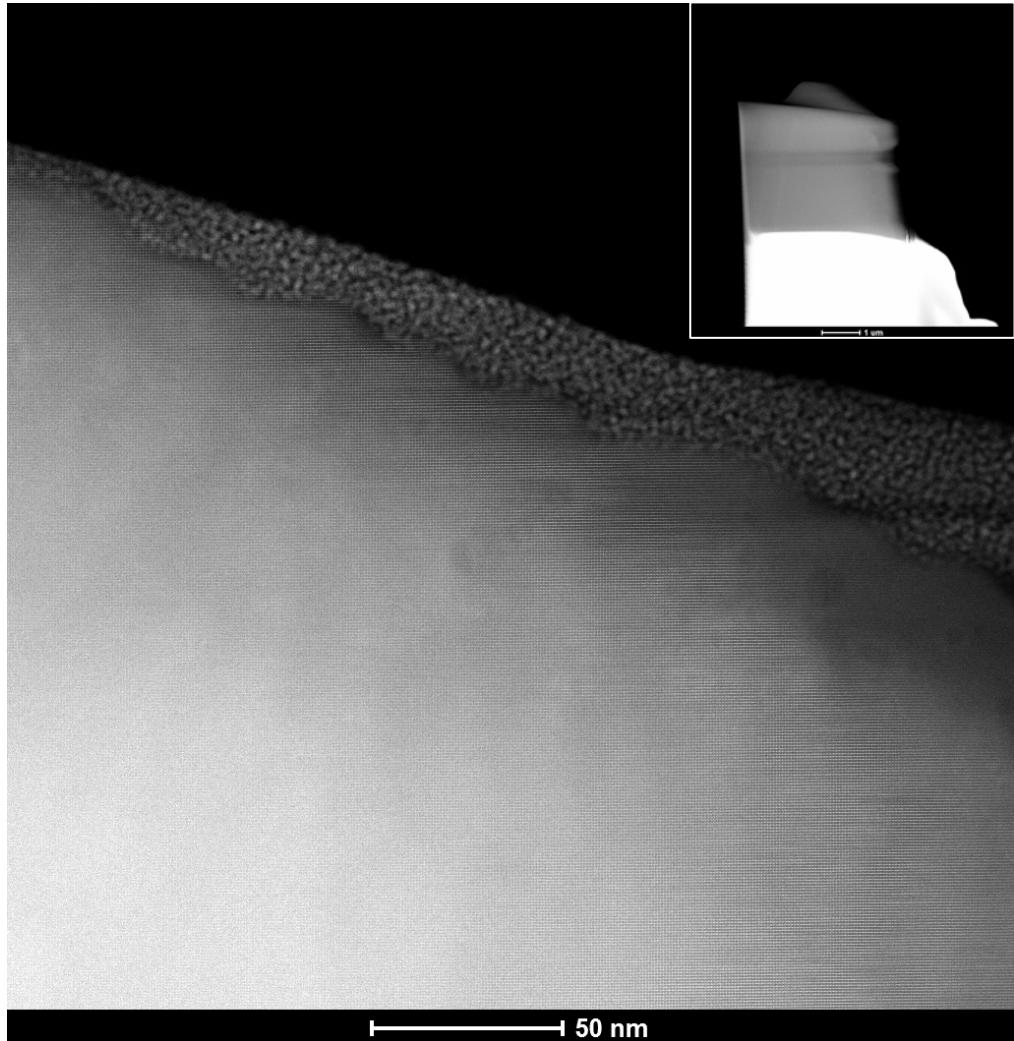
Ga



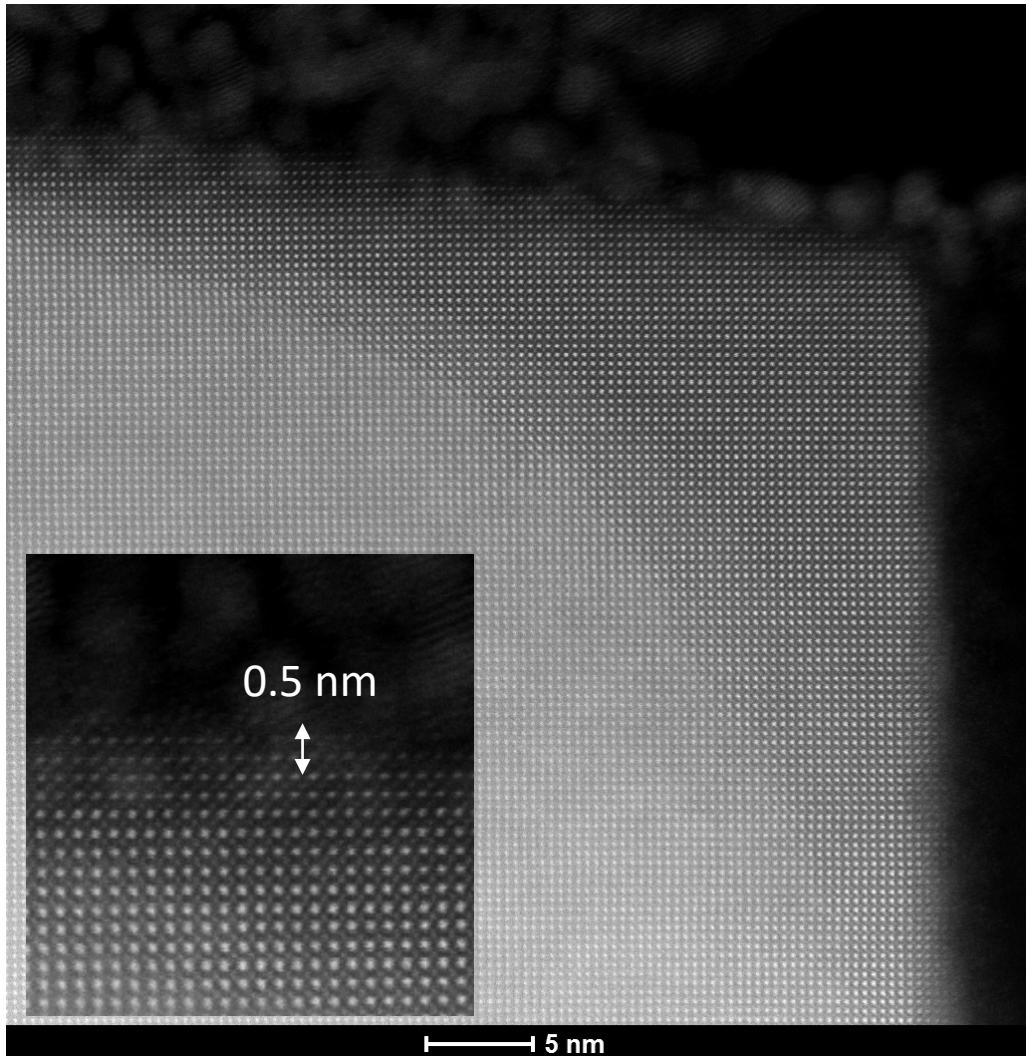
O₂



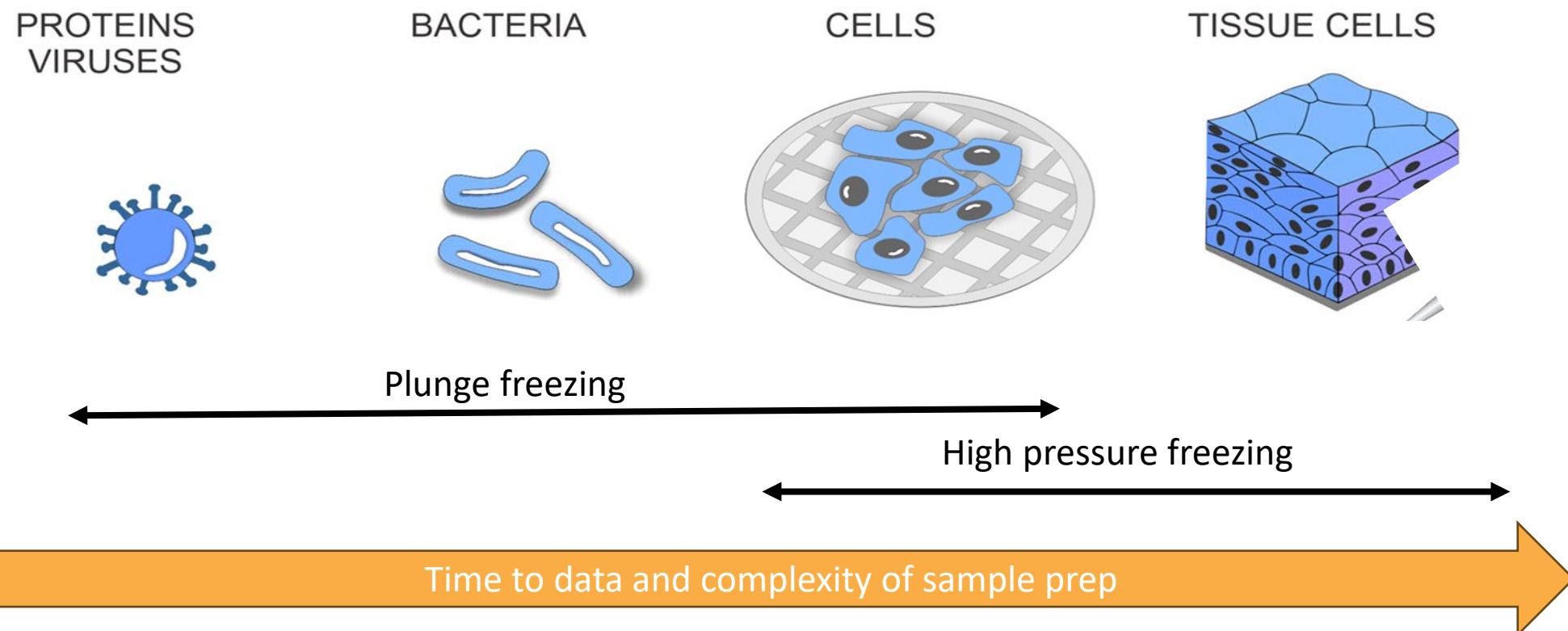
Damage on BFO using Xe



Damage on BFO using Ar



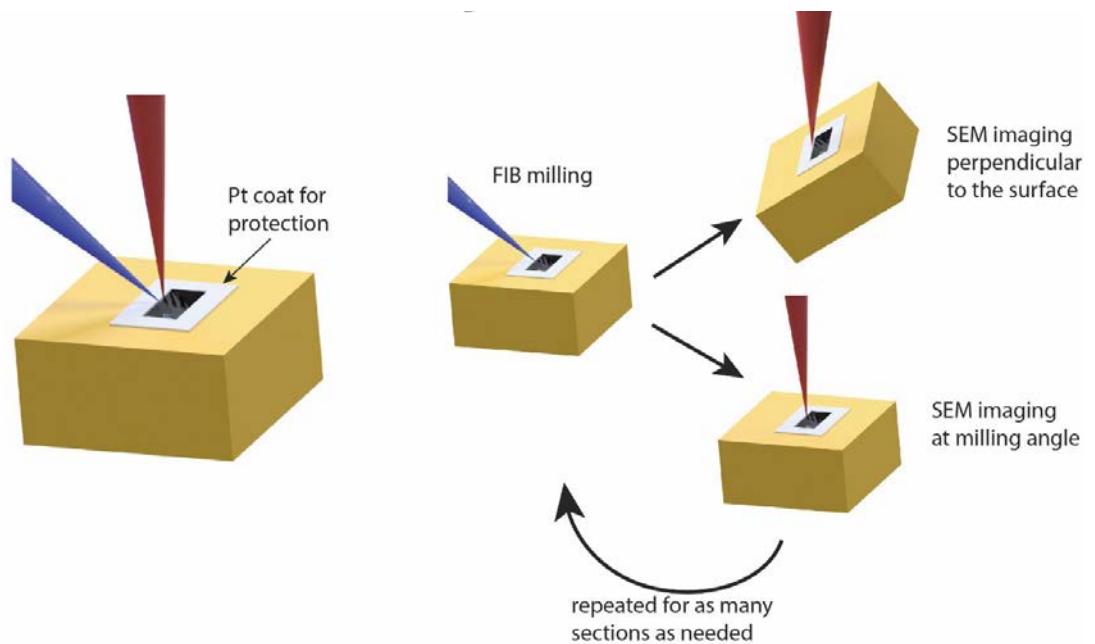
Samples



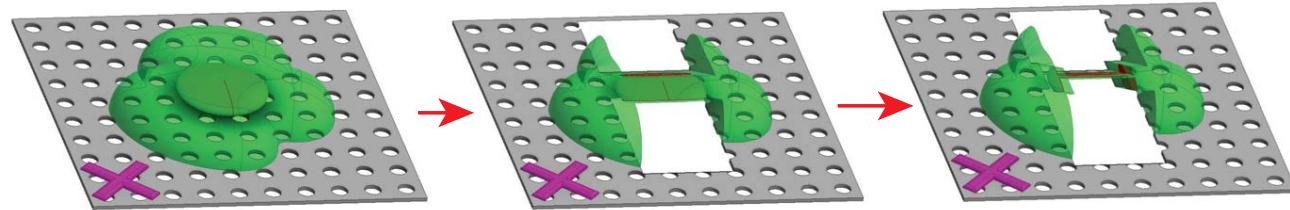
Adapted from Klumpe et al Mic today 2022

FIB in life sciences

FIB/SEM tomography



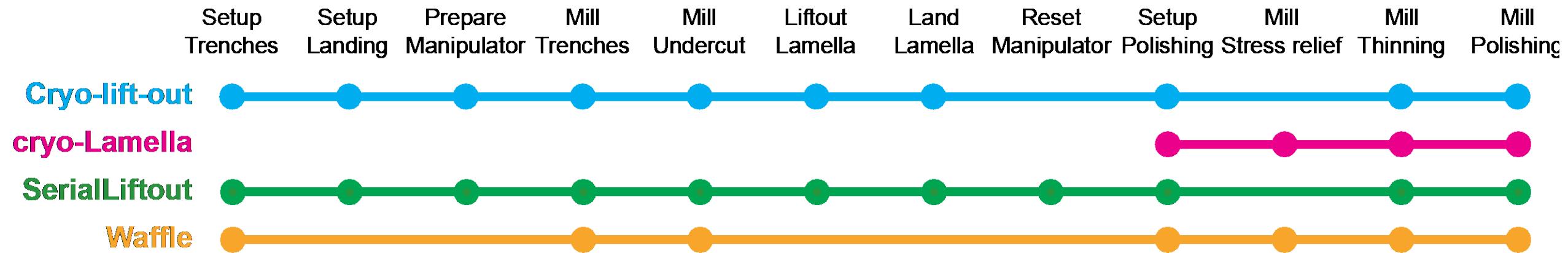
Cryo-lamella preparation



The sample preparation protocol is defined by the sample

3D Imaging is typically performed over tens of microns at 5-20 nm resolution

FIB workflows are all the same

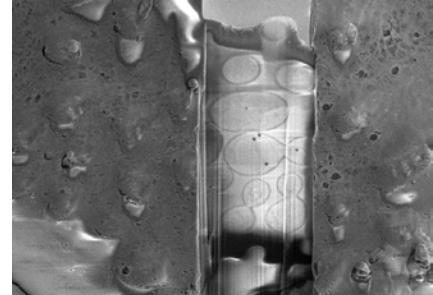
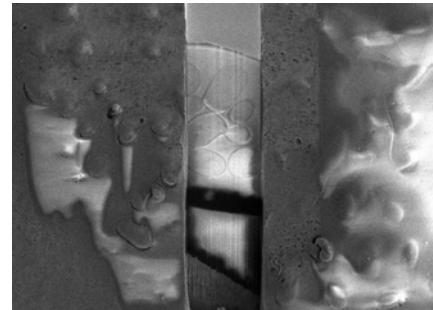
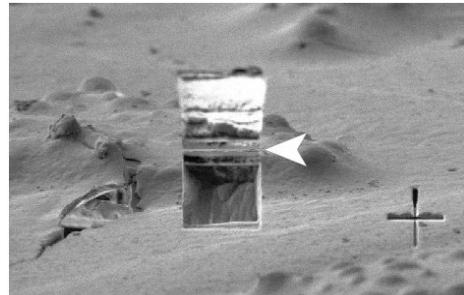
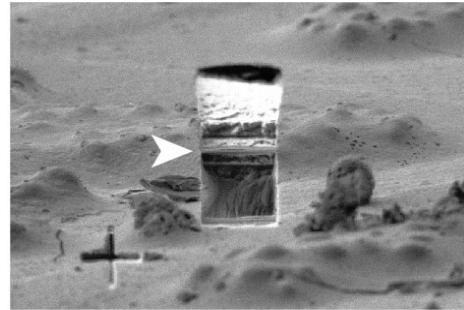
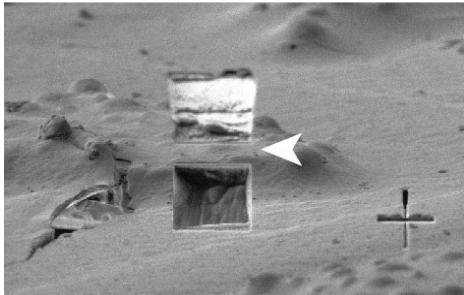
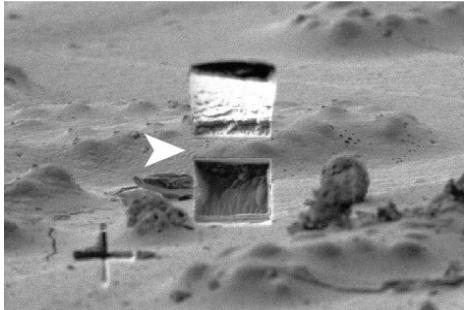
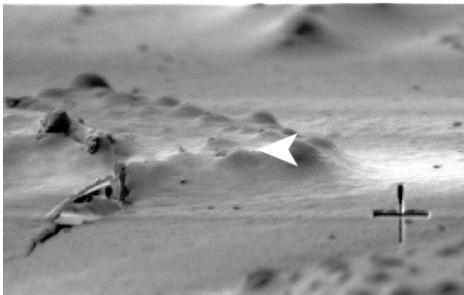
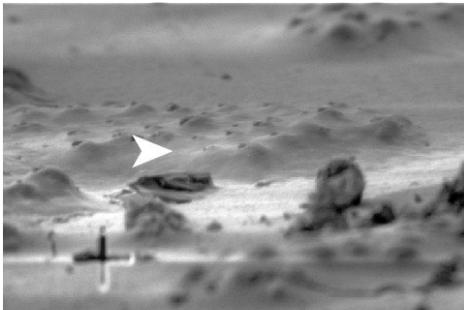


Automated lamella preparation

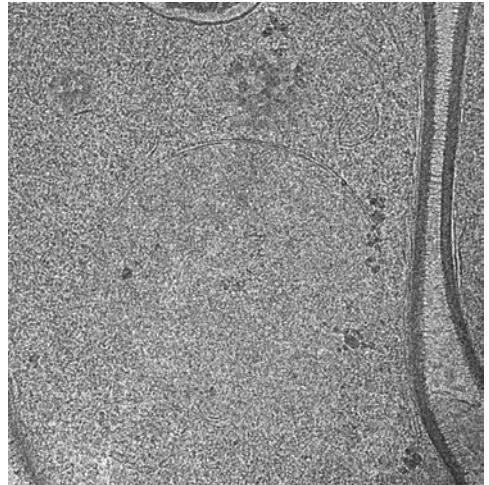
Select ROIs

Rough milling

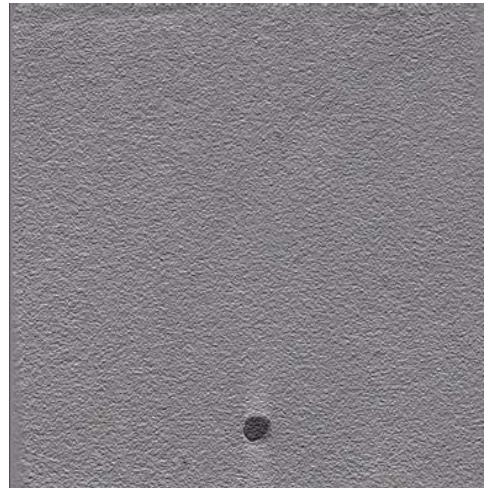
Polish



Low mag cryo-TEM



Cryo-ET

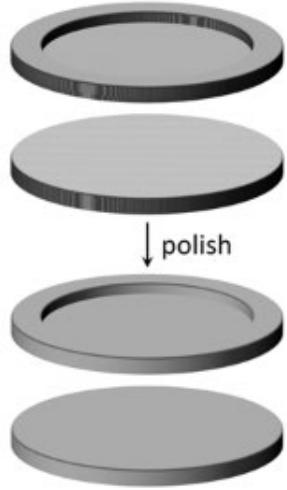


**Batch lamellae preparation leads to up
to 4-6 lamellae / hour**

For thicker samples - waffle

Step 0: Prepare hardware

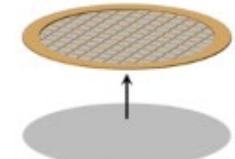
a) Polish planchette hats



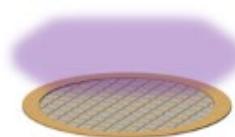
b) Coat with 1-hexadecene



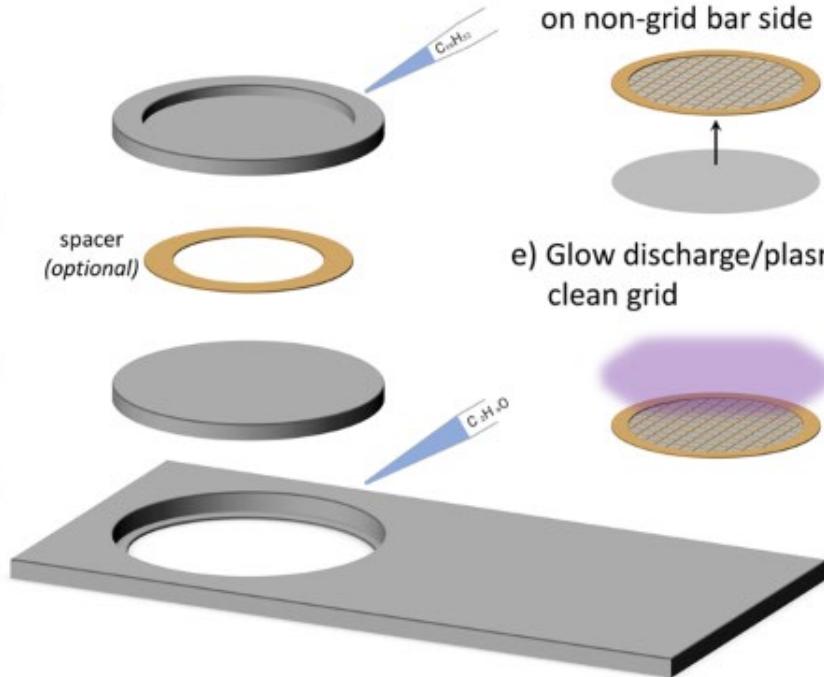
c) Sputter ~25nm carbon coat on non-grid bar side



e) Glow discharge/plasma clean grid

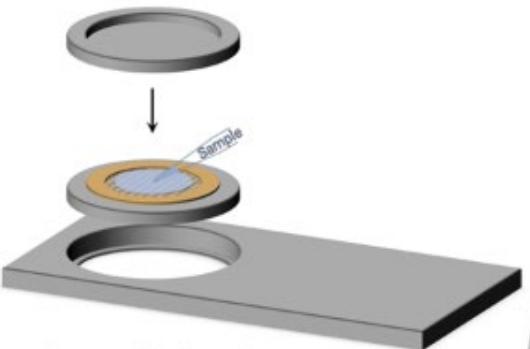


d) Clean HPF tip with ethanol



Step 1: Make Waffle

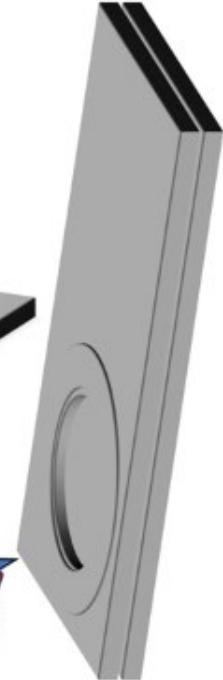
f) Apply sample to waffle mold



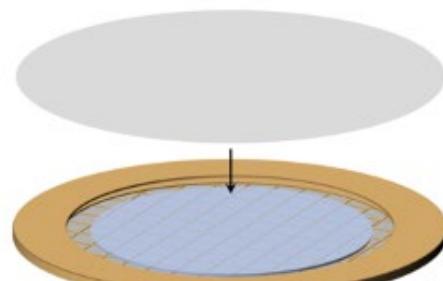
*may be assembled inside or outside of the HPF tip



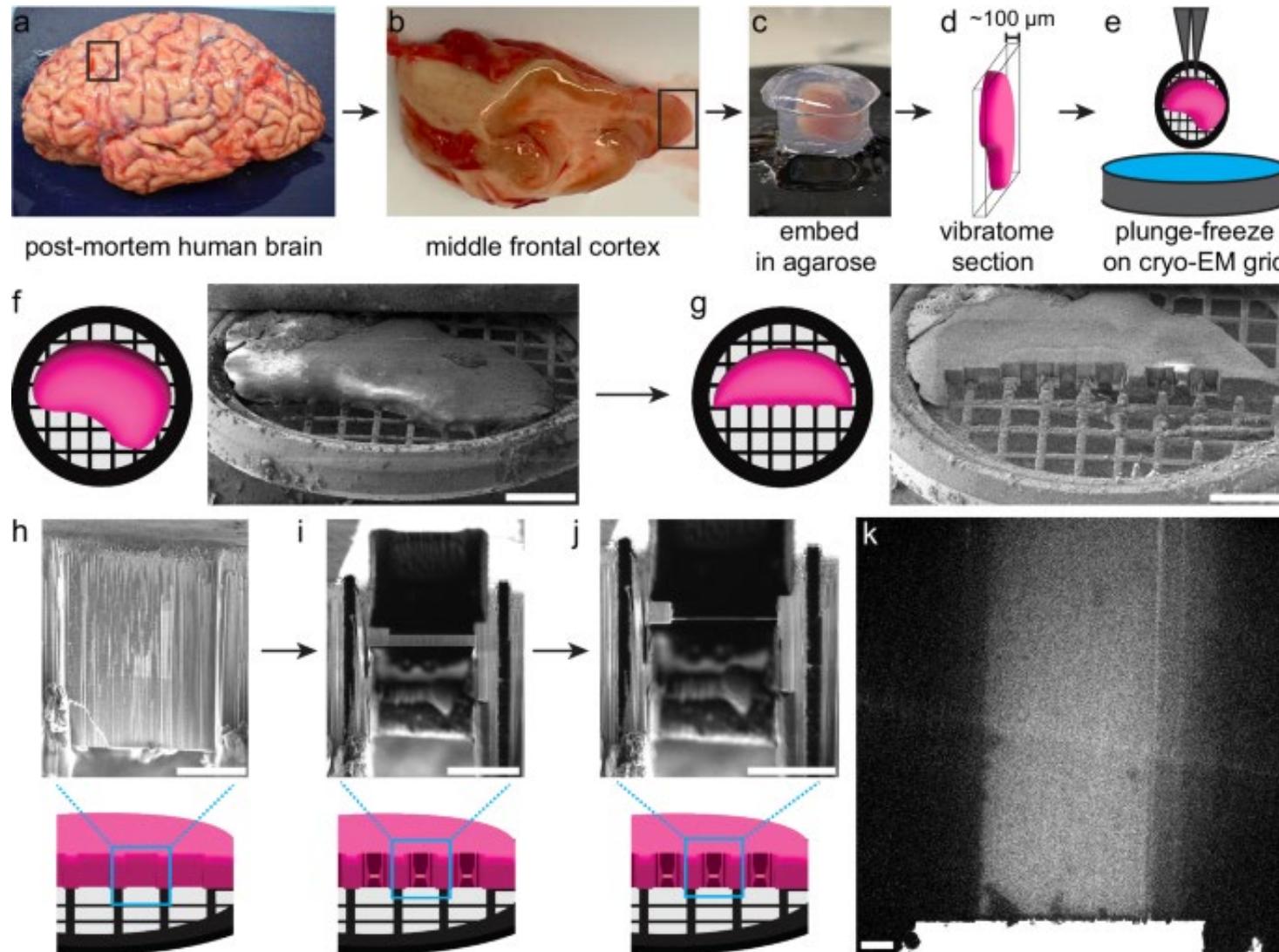
g) HPF sample



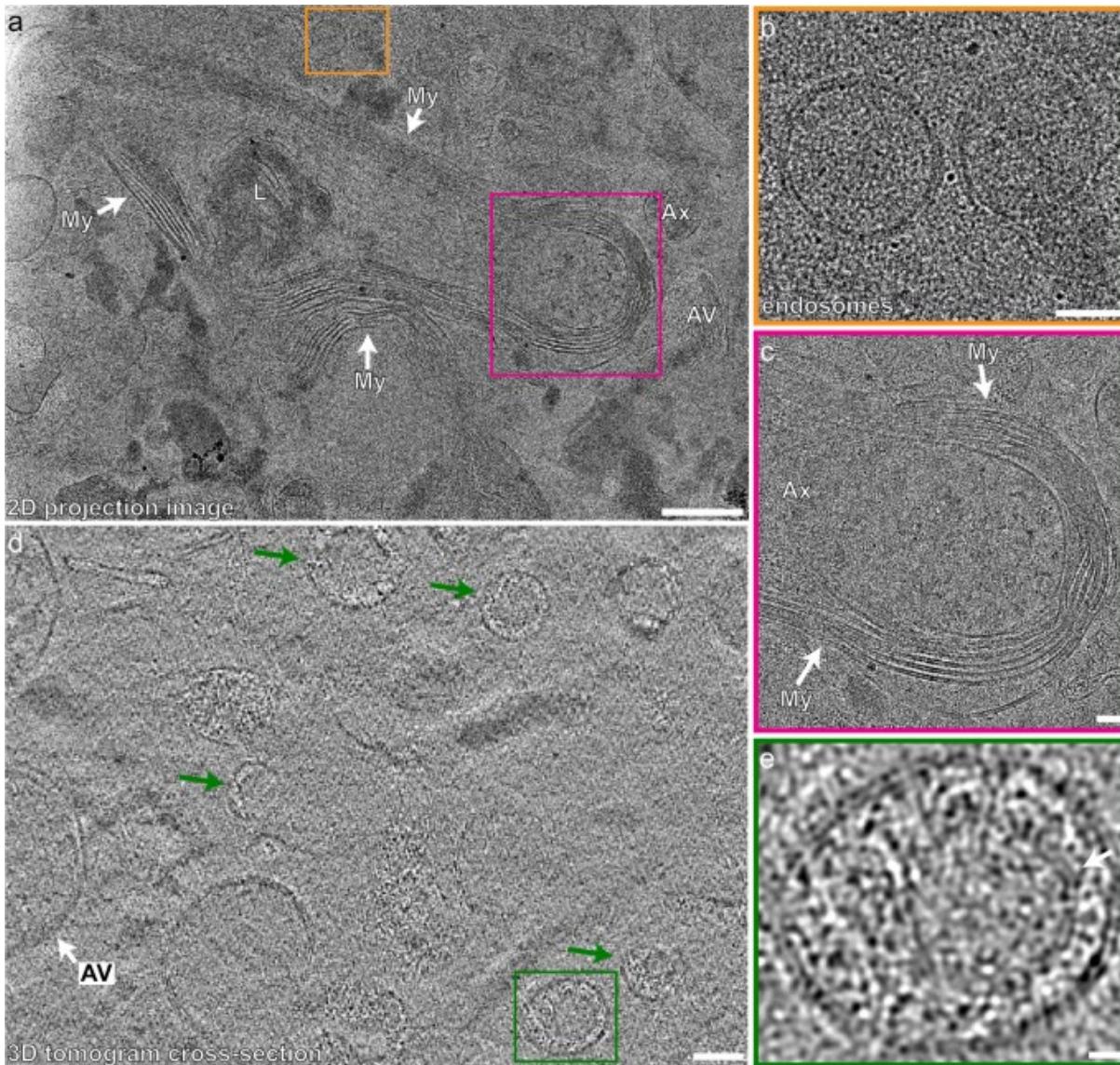
h) Disassemble, clip grid, and (optional) sputter on ~5nm of platinum



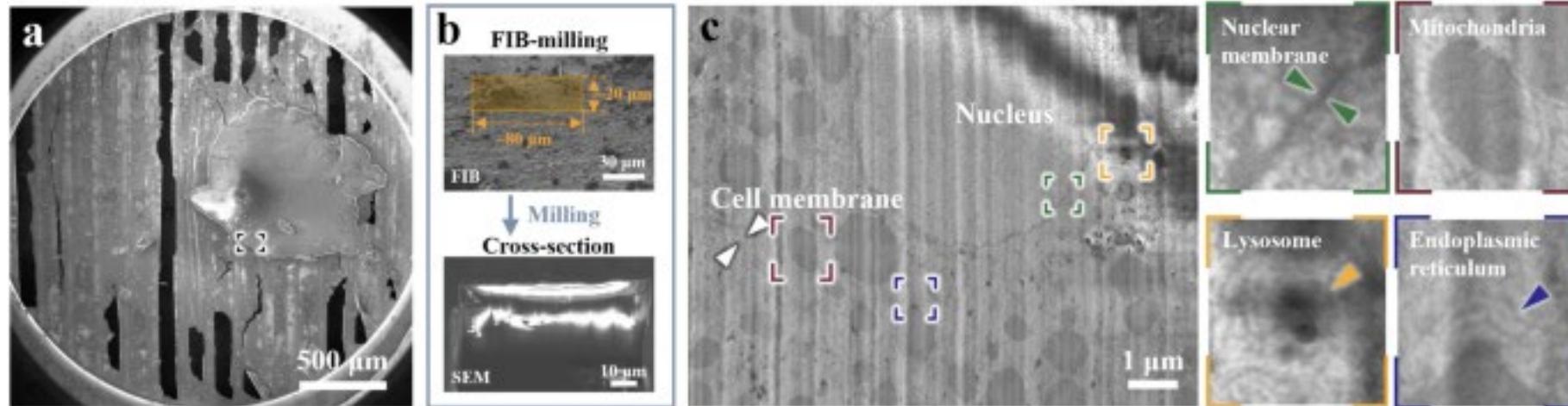
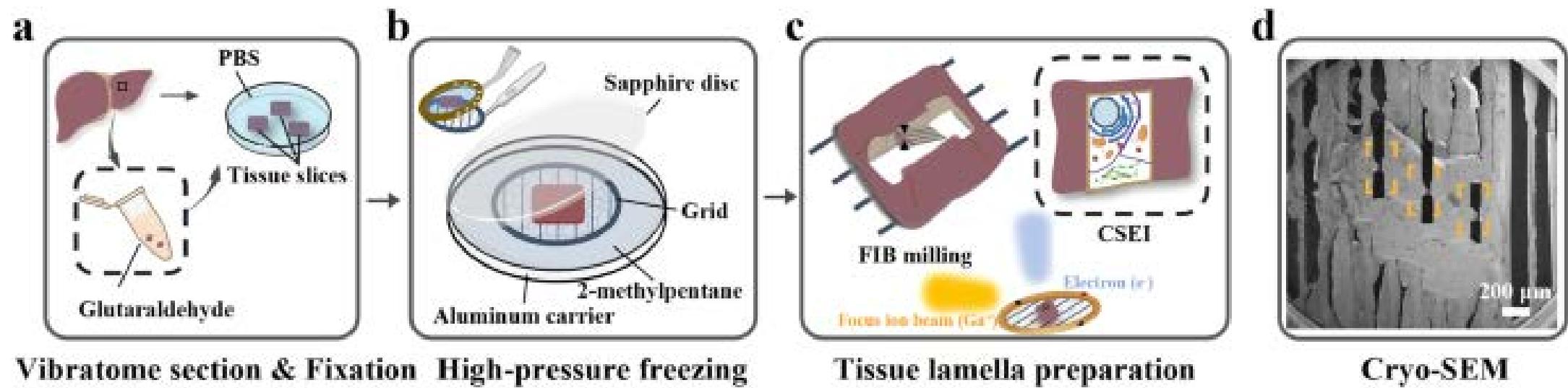
On-site lamellae in tissue sections



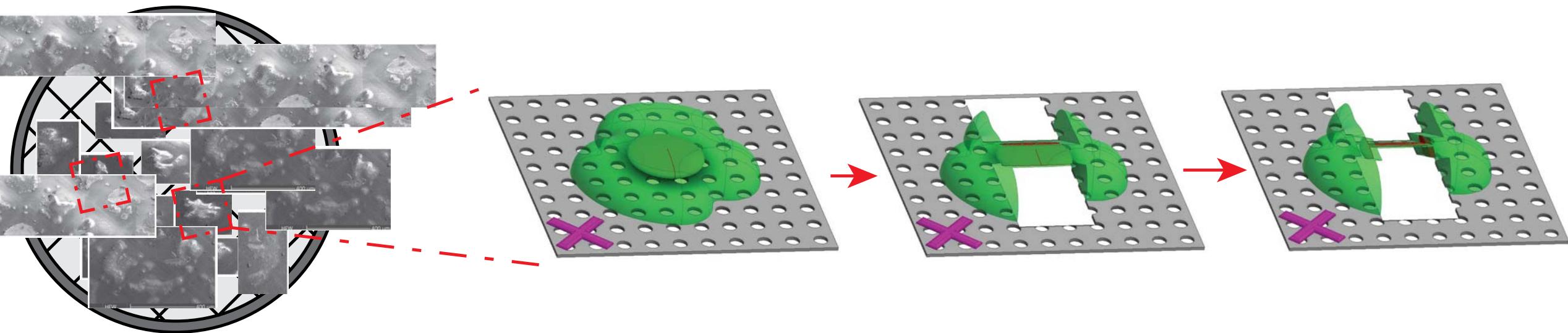
On-site lamellae in tissue sections

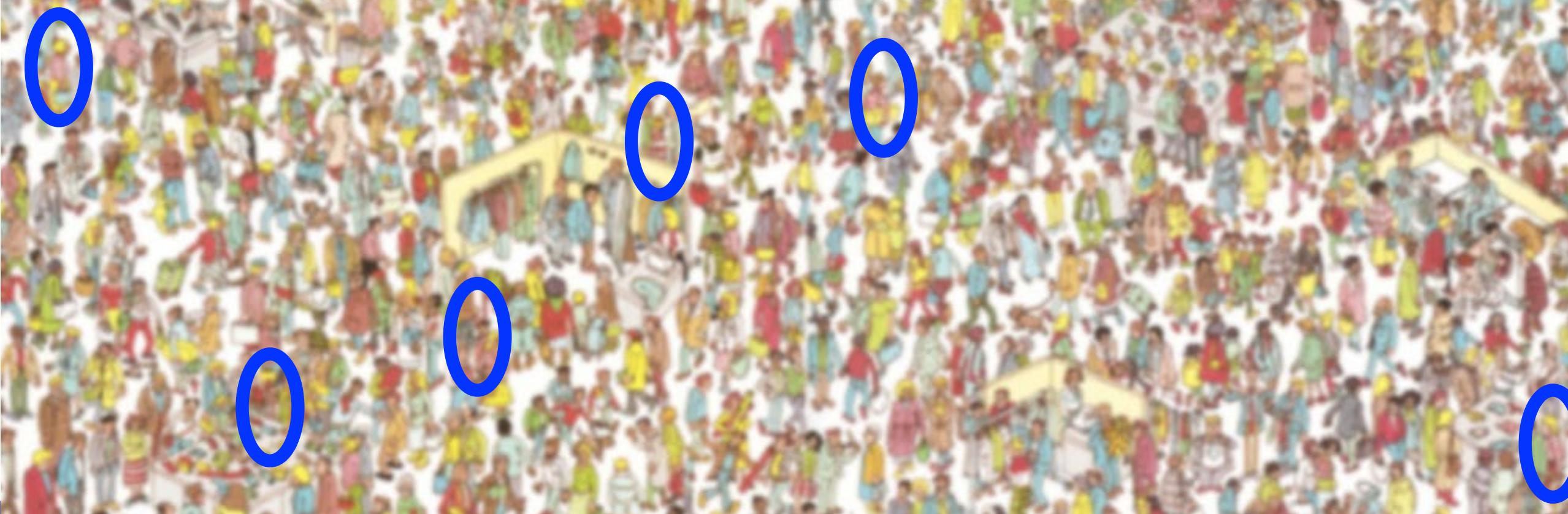


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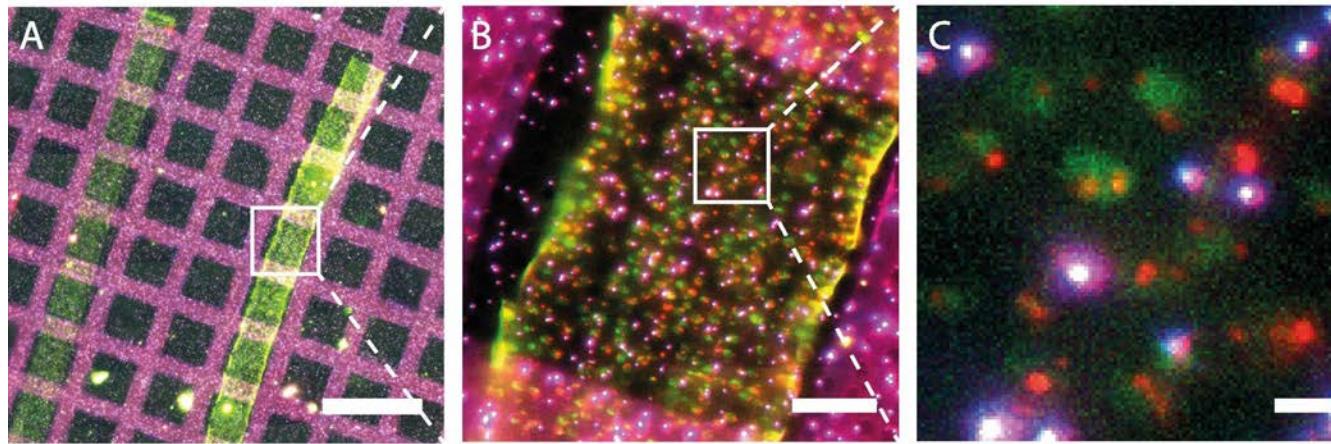
Cryo lamella preparation



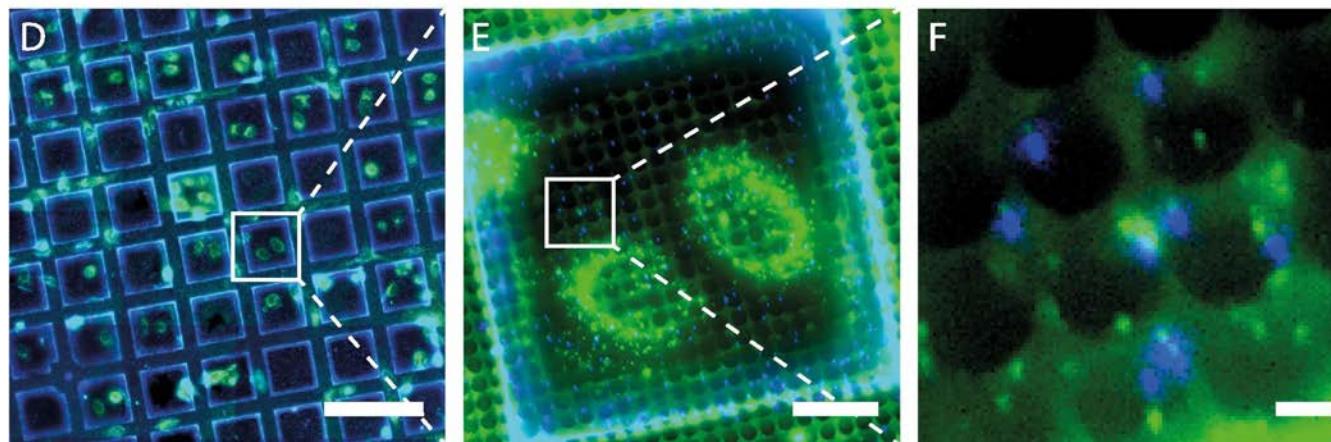


Cryo-Light Microscopy

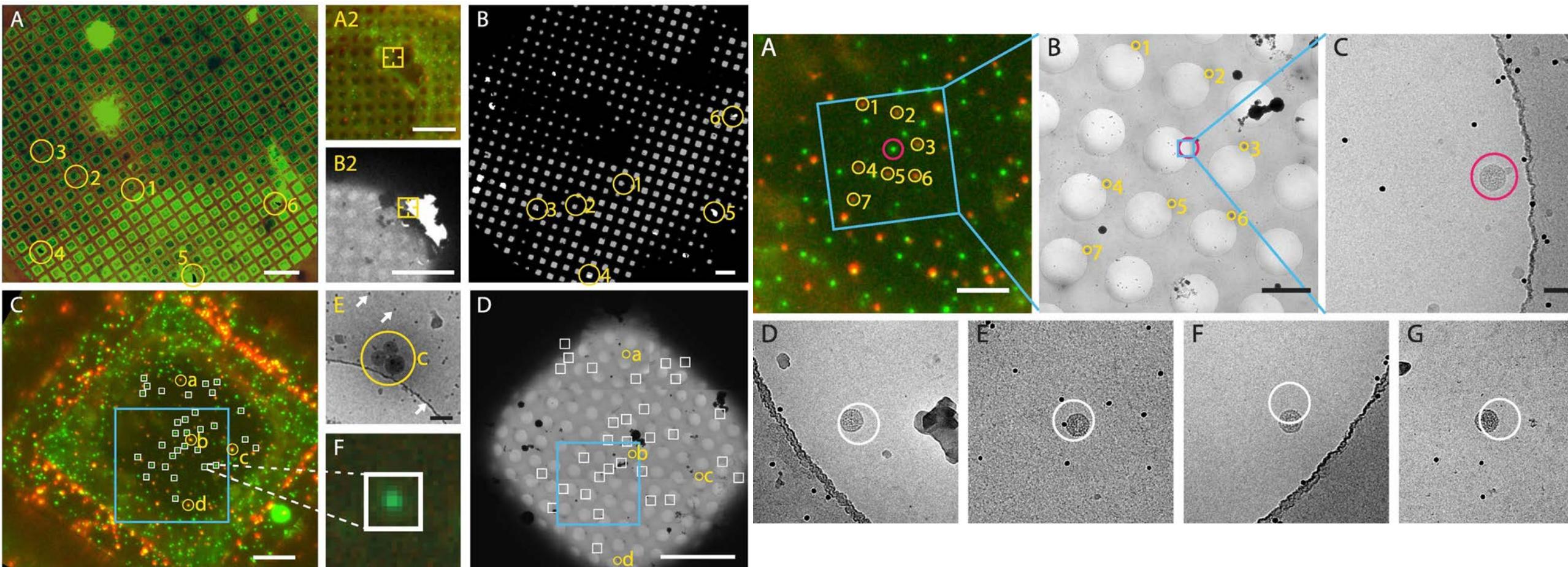
CEMOVIS



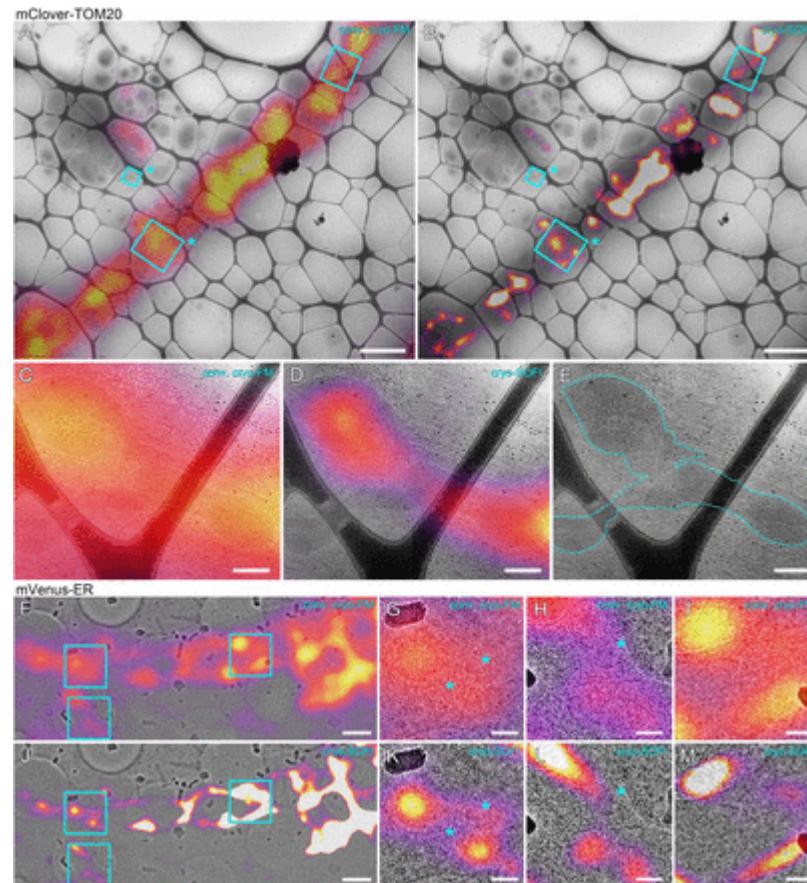
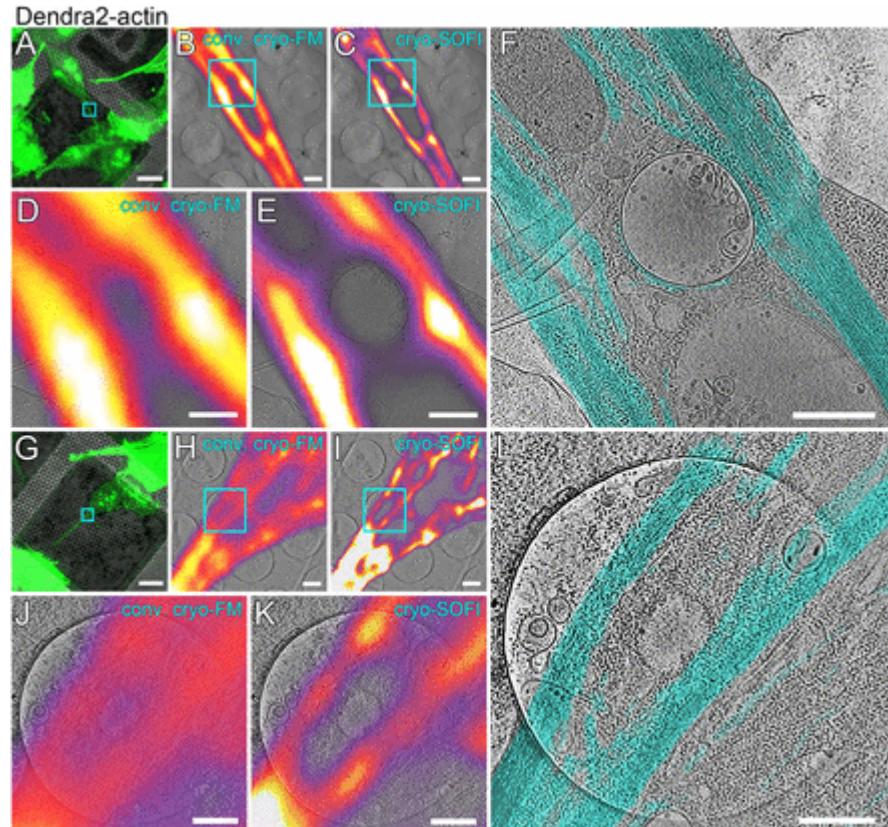
Culture on grid



Cryo-CLEM

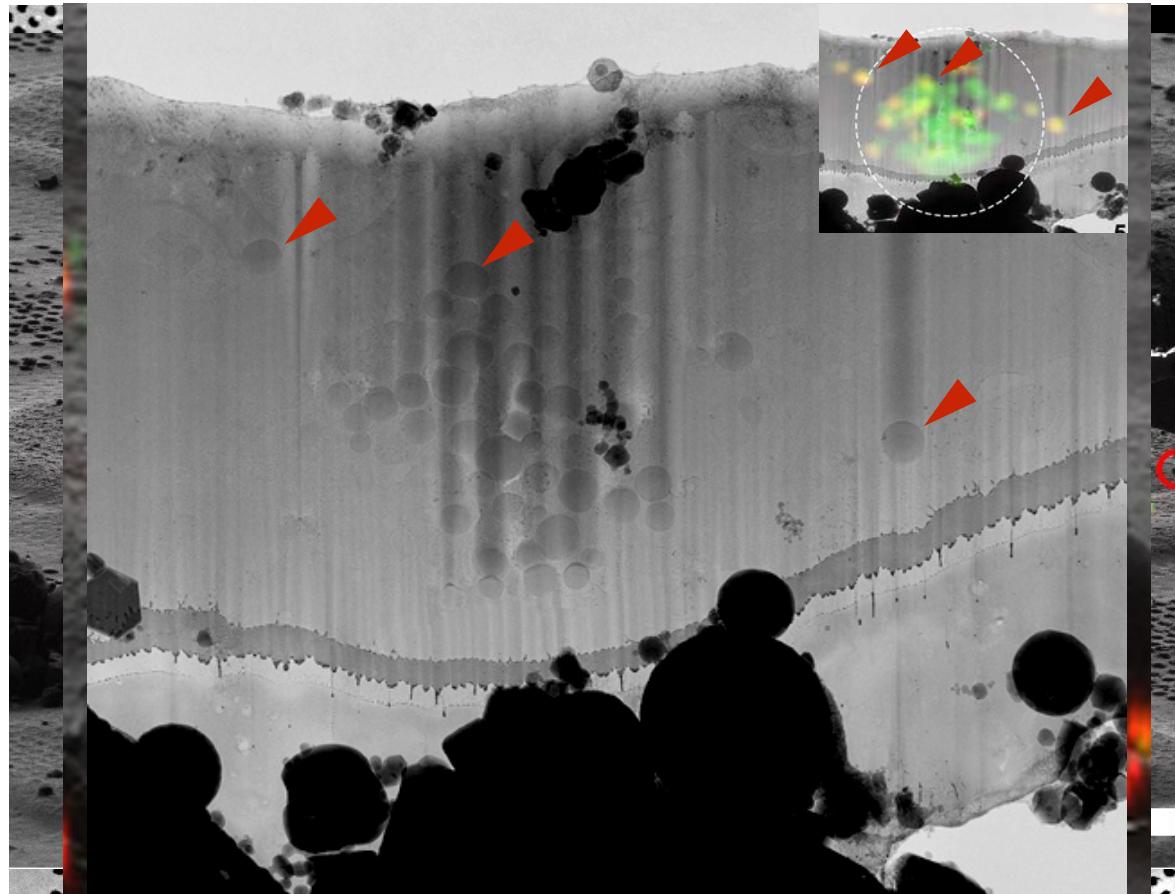


Super resolution Cryo-Light Microscopy (SOFI)

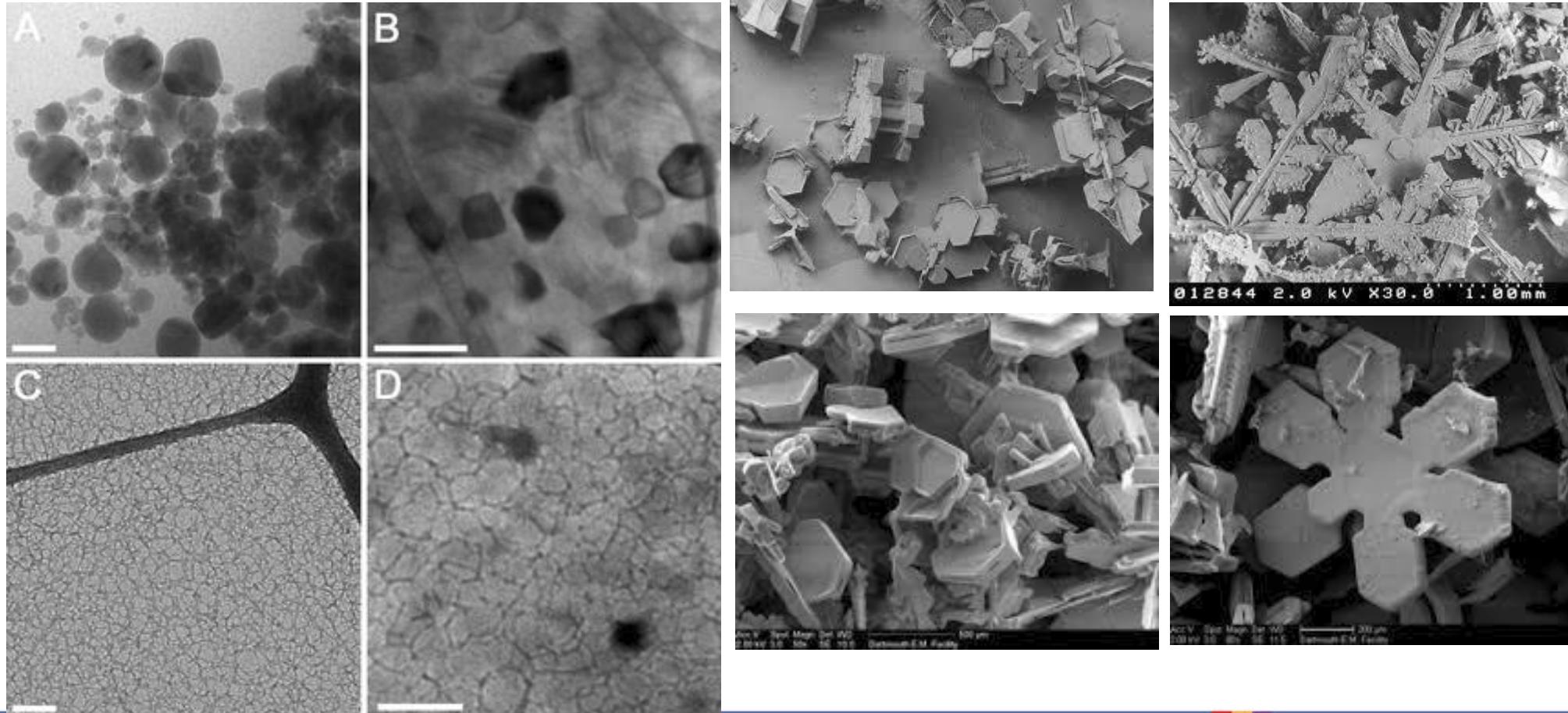
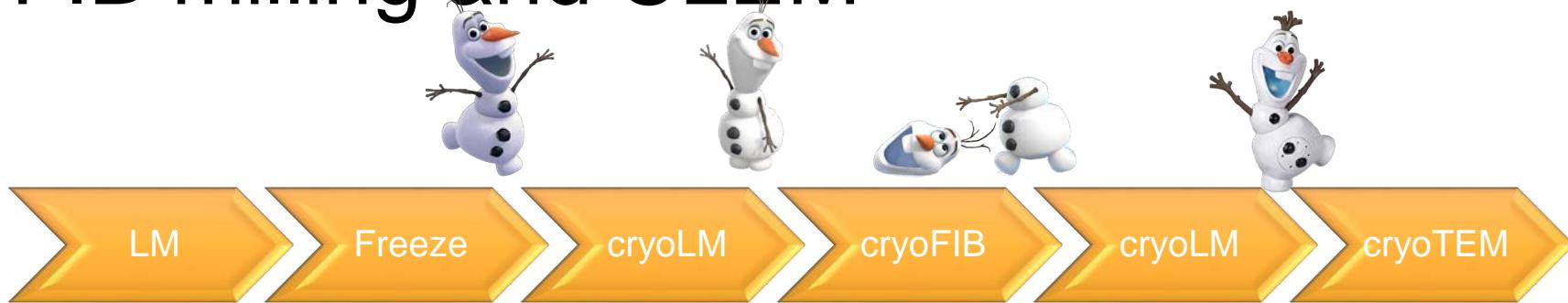


An example of 3D correlation:

- Localise a cluster of lipid droplets in mammalian cells



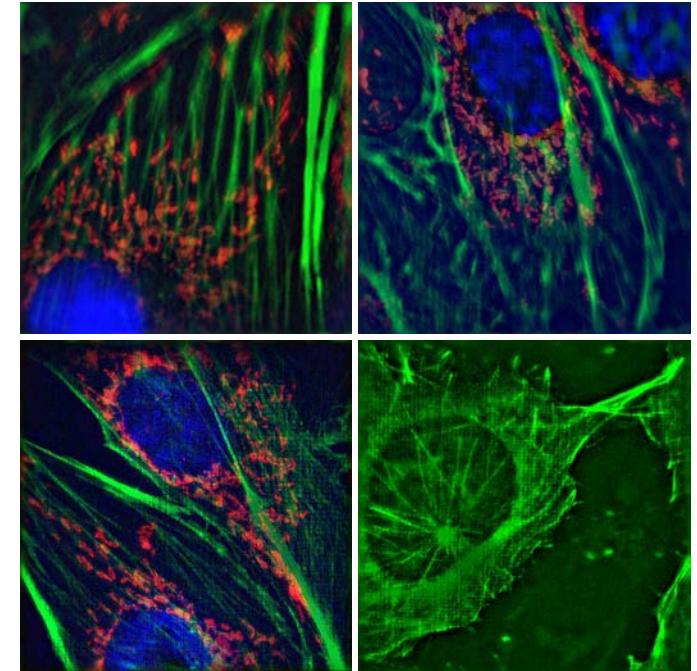
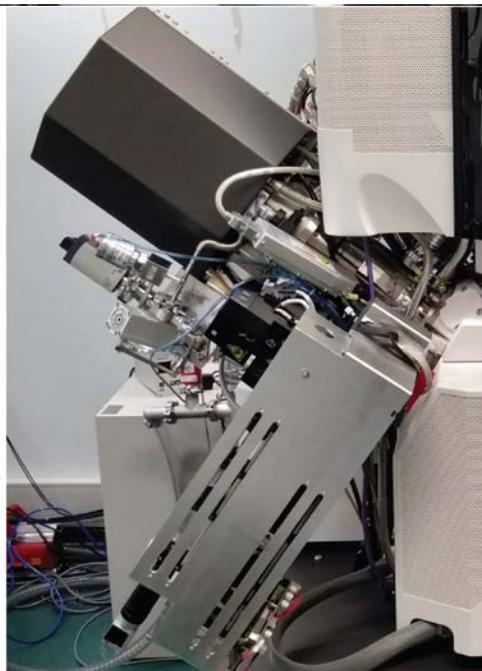
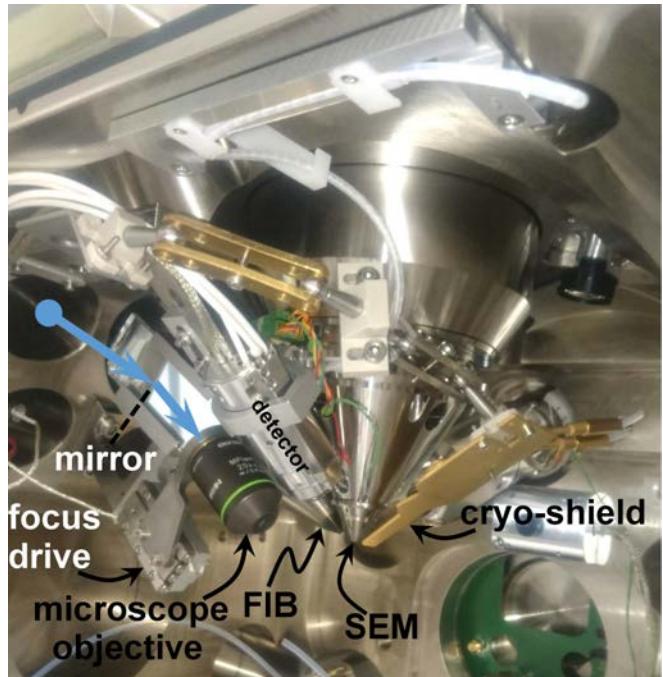
Cryo-FIB milling and CLEM



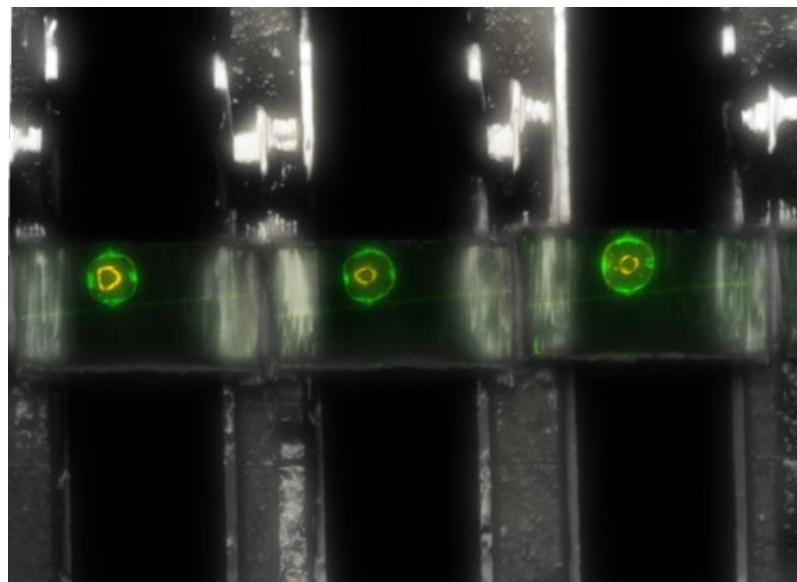
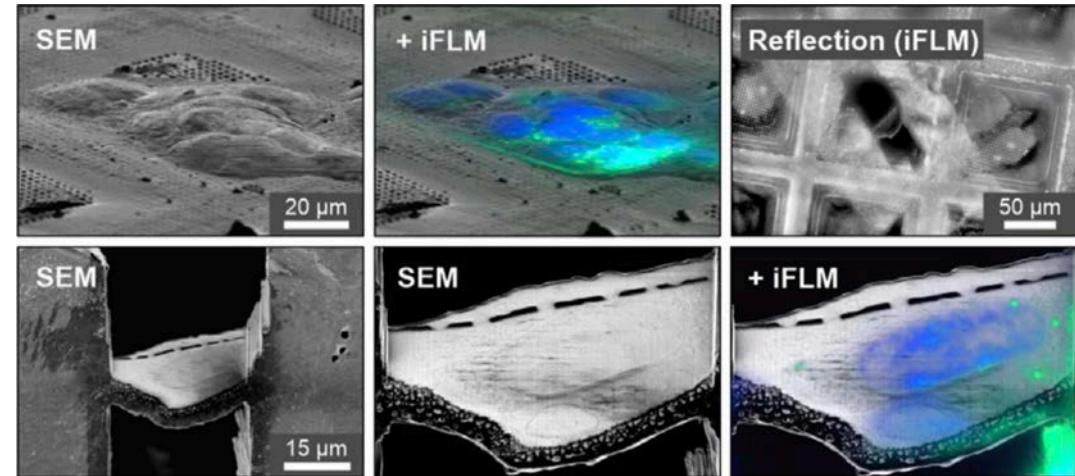
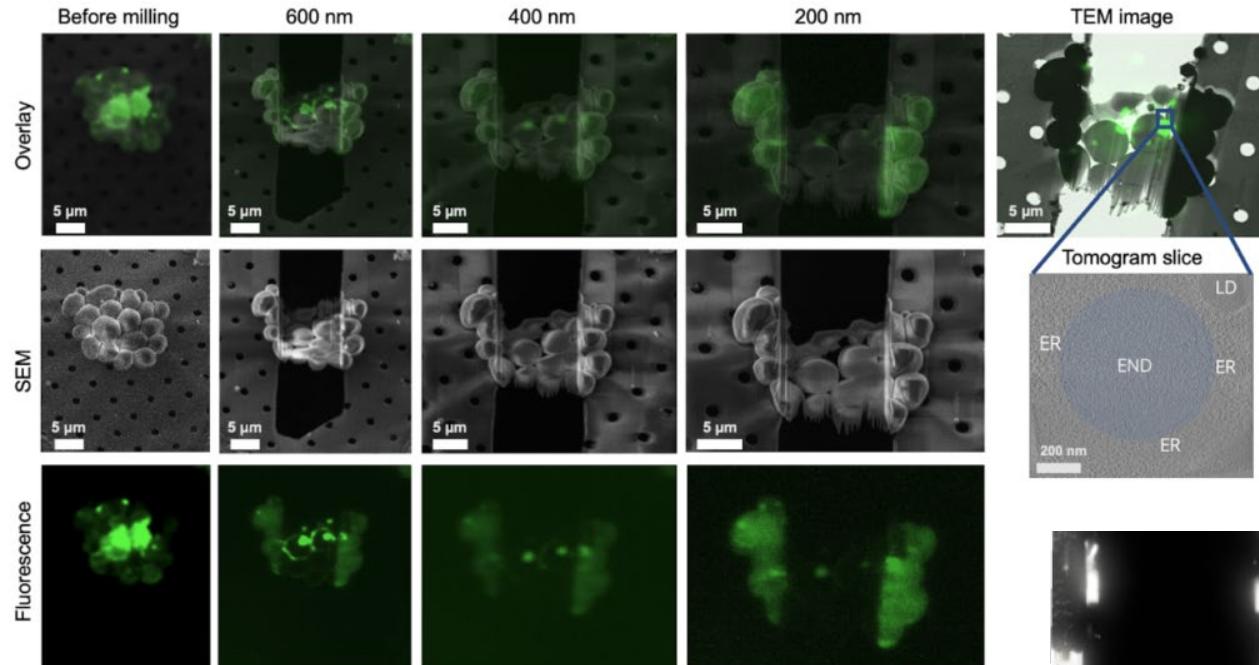
cryo-CLEM



sr PIE-scope

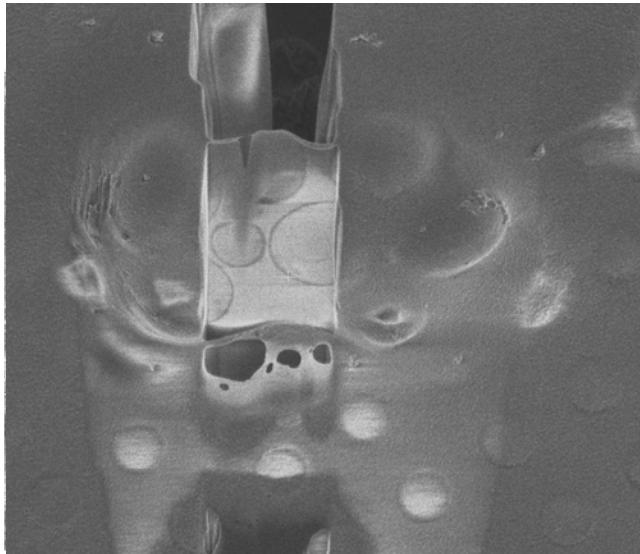


Uses of integrated FIB/LM

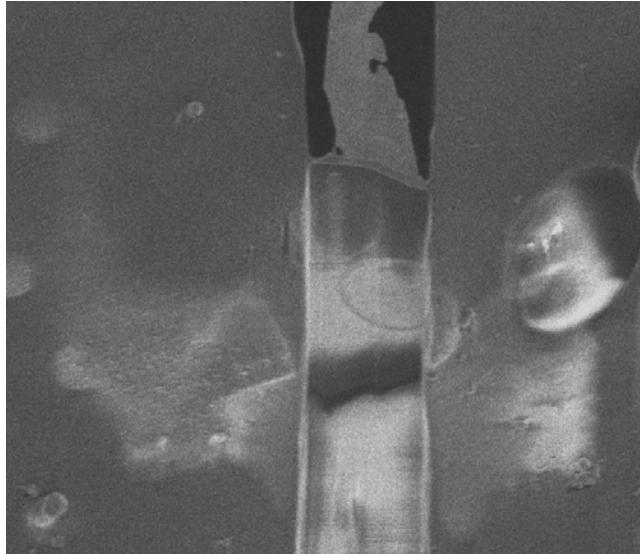


PFIB for cryo-lamella prep

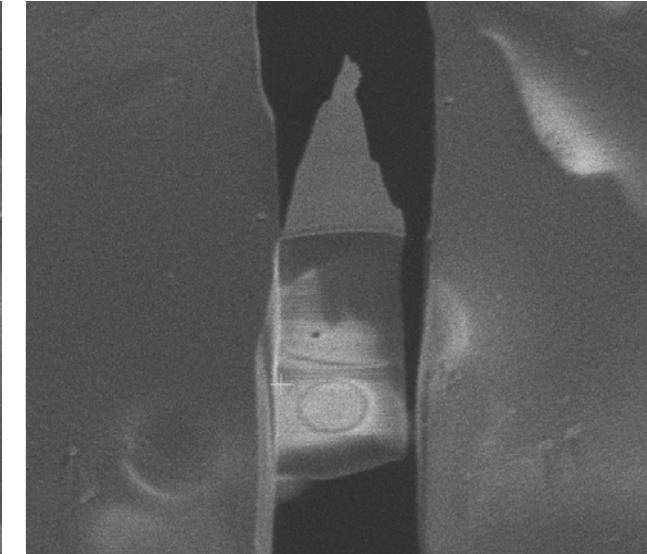
Ga



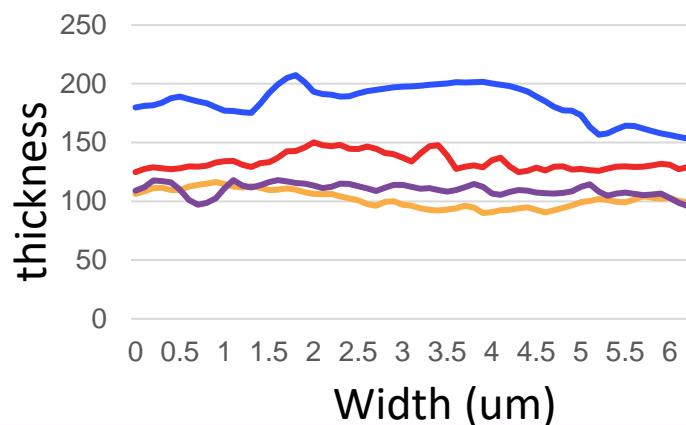
Xe



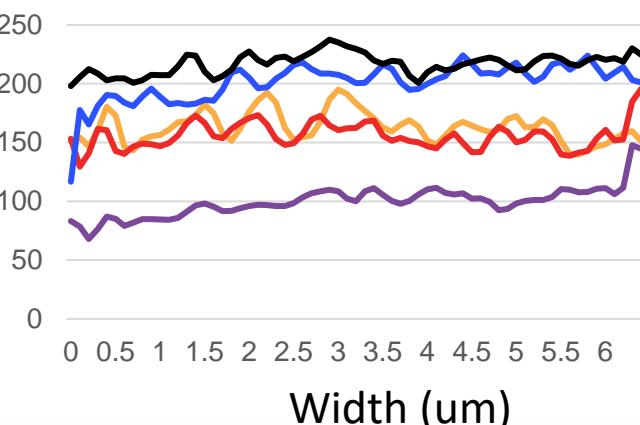
Ar



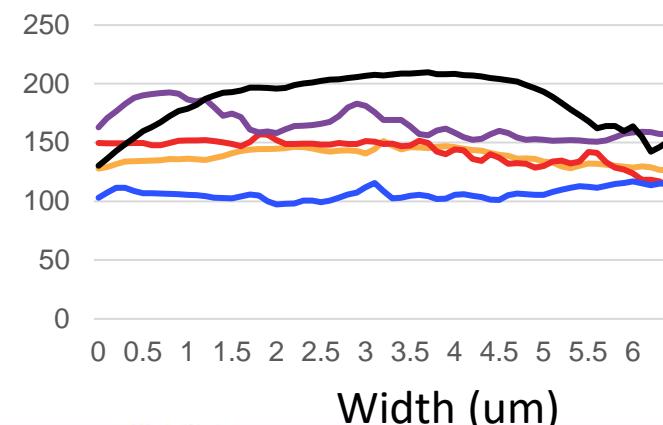
9 Min



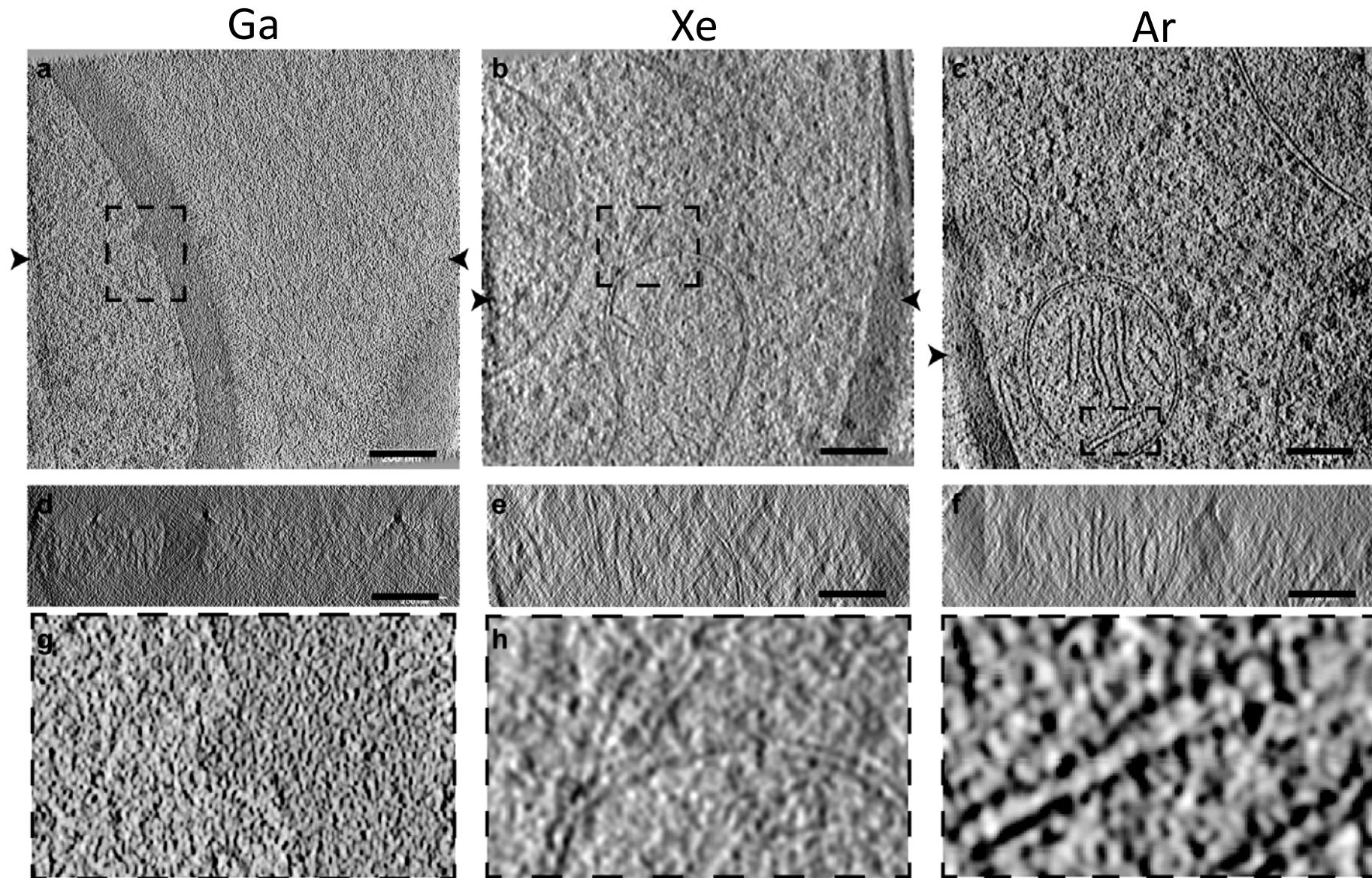
15 Min



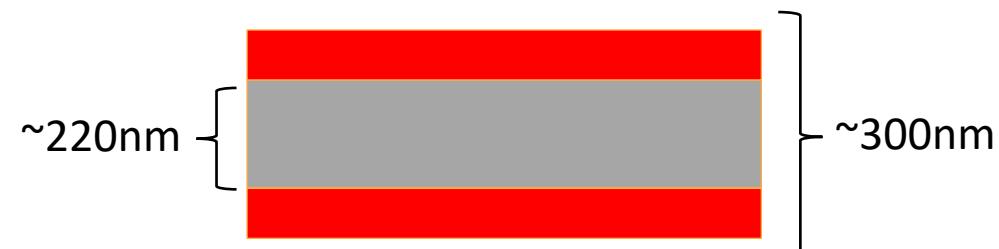
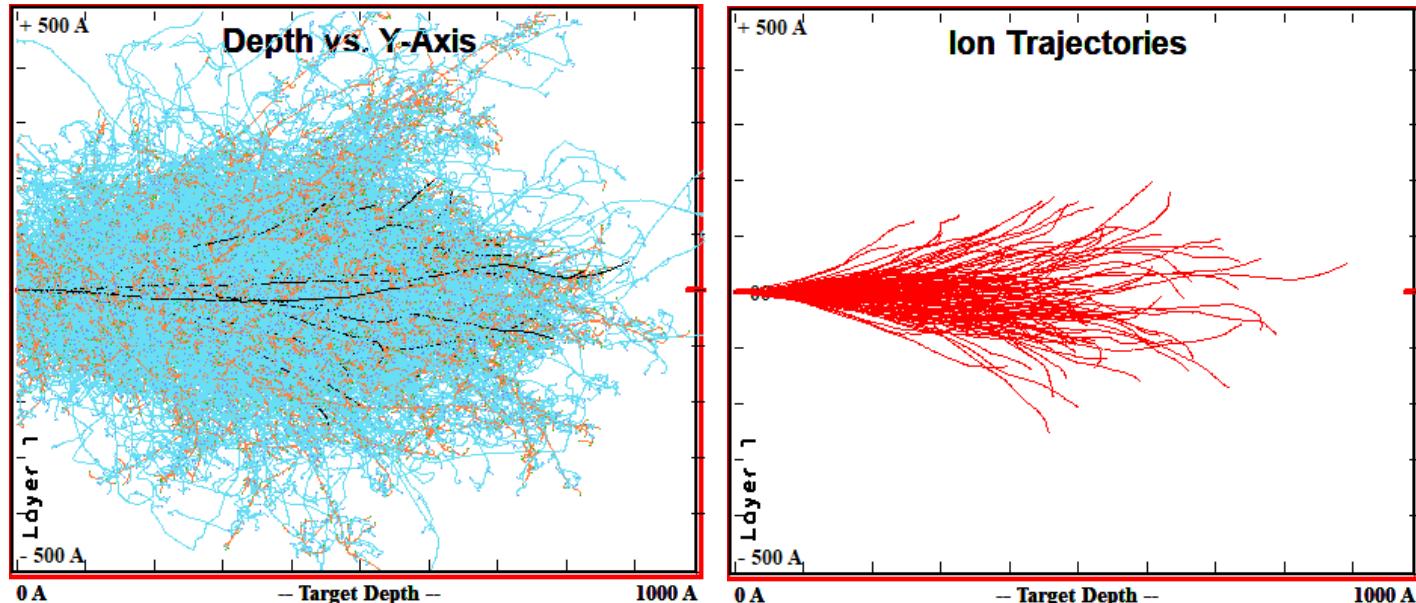
7 Min



PFIB for cryo-lamella prep

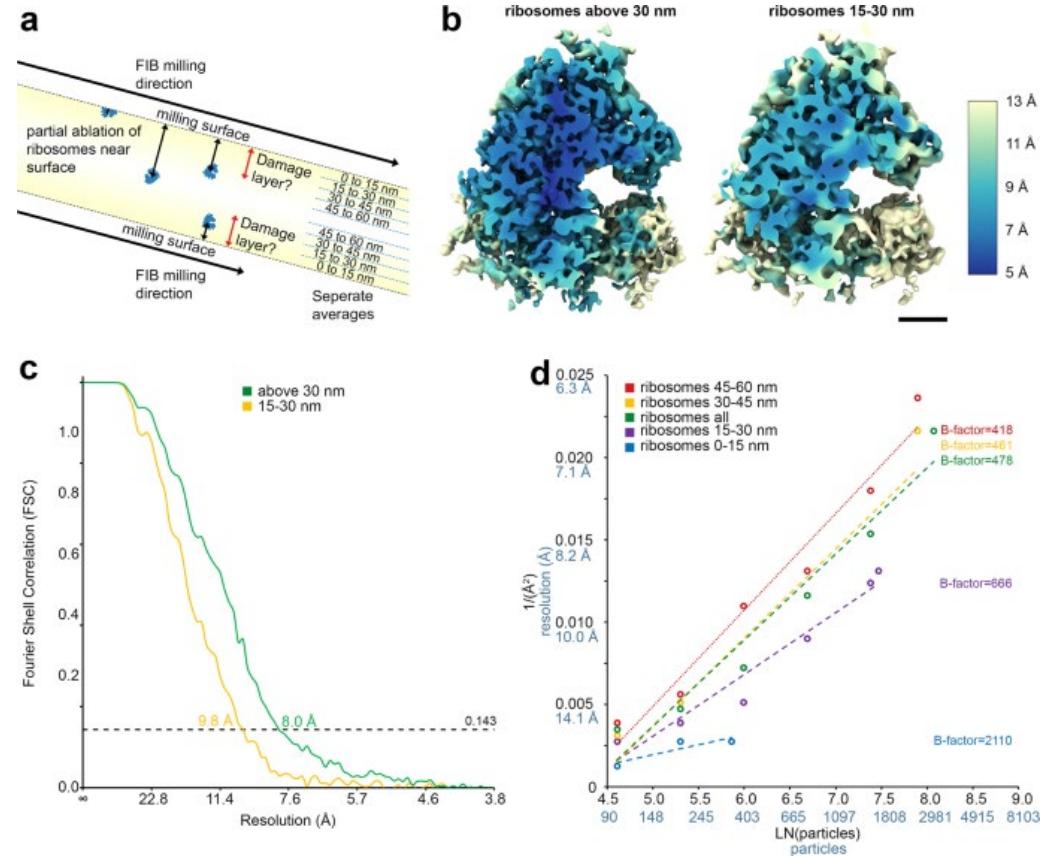
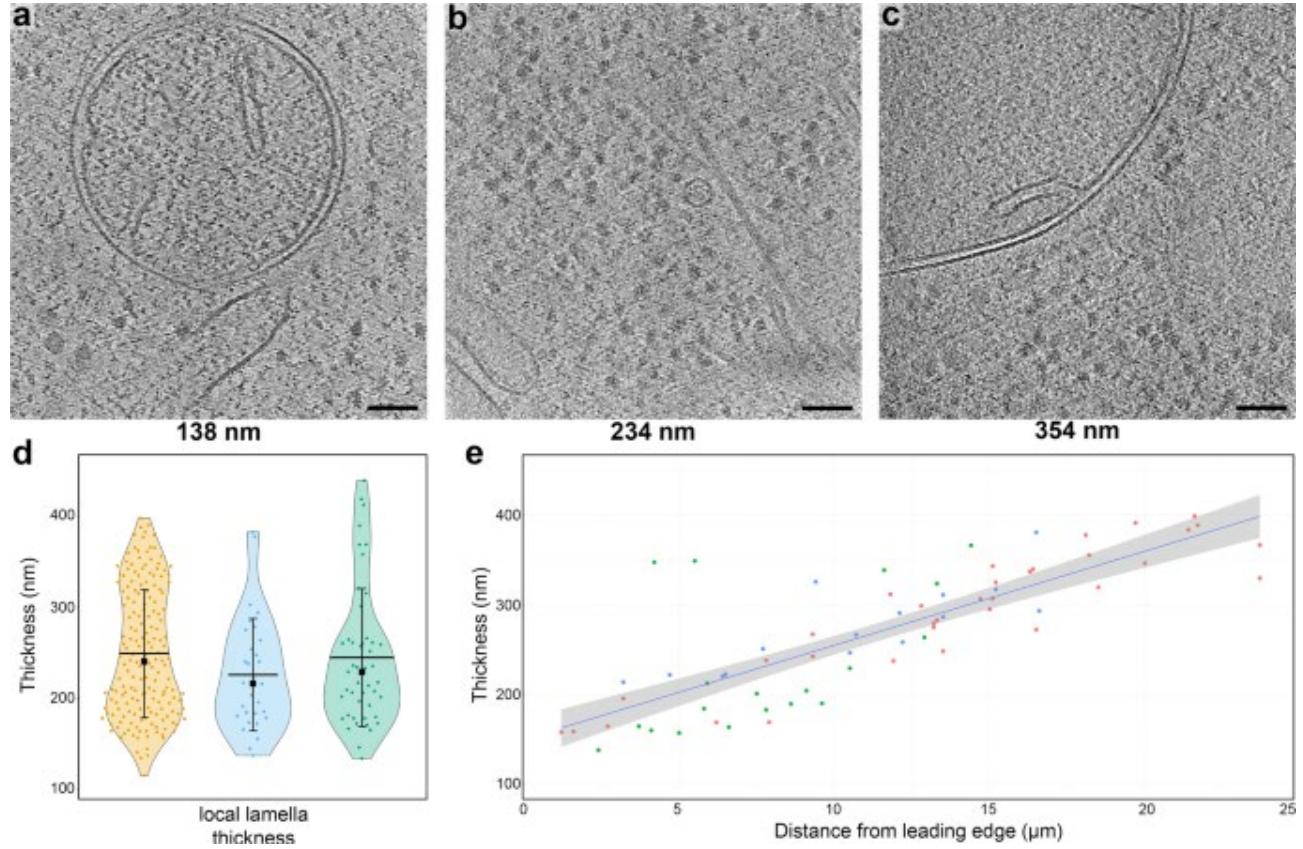


Cryo lamella preparation using plasma

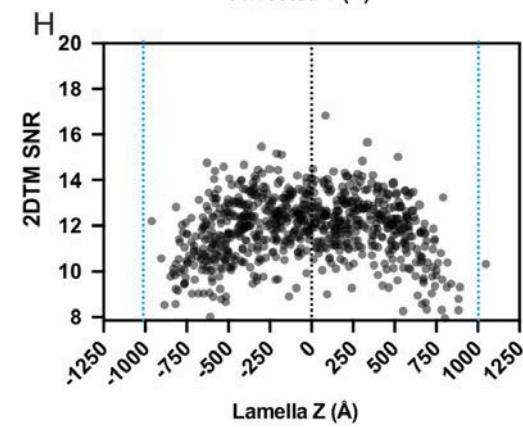
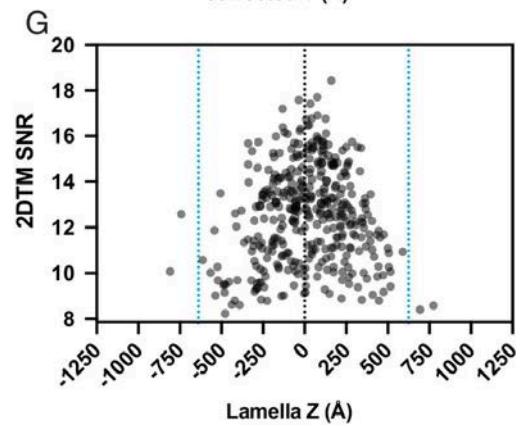
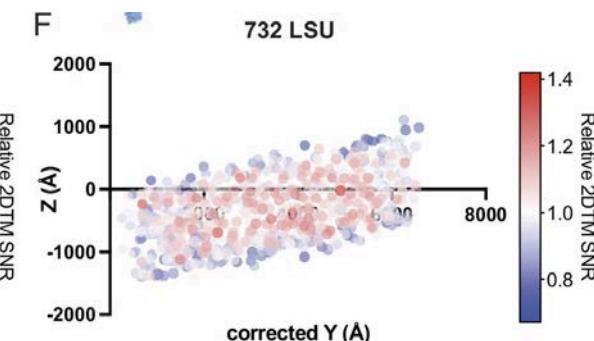
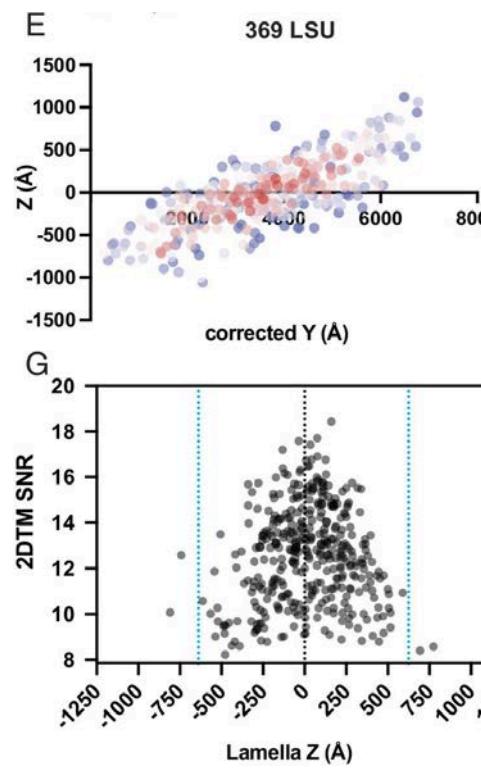
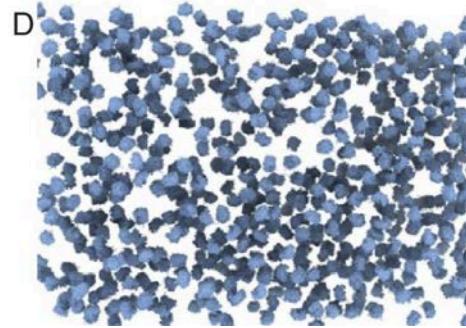
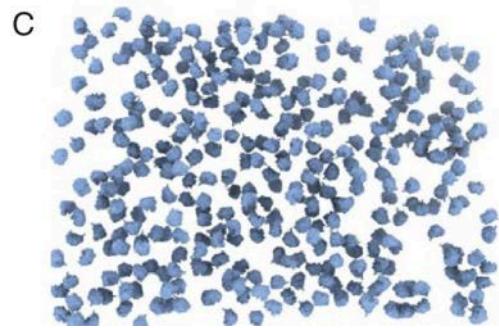
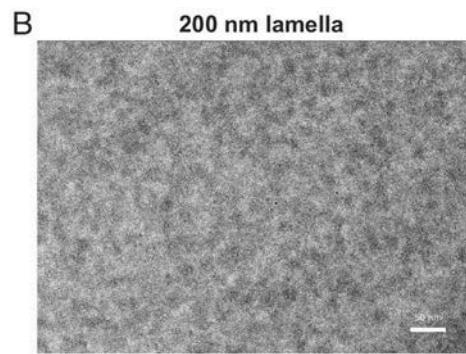
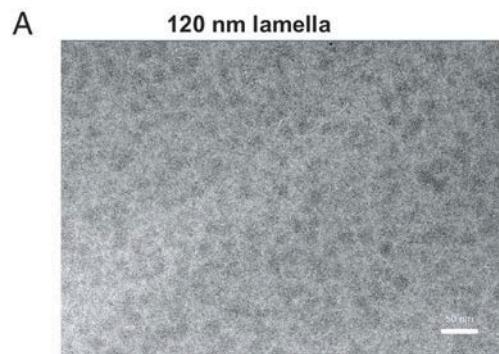


Plunge-frozen yeast

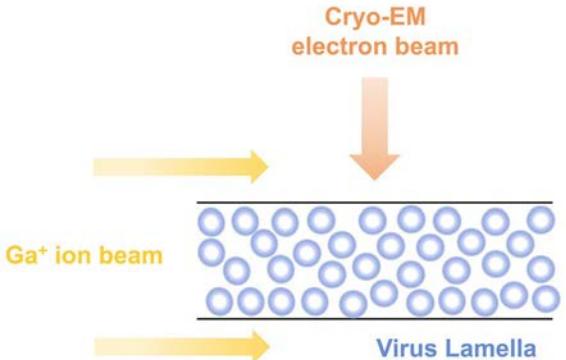
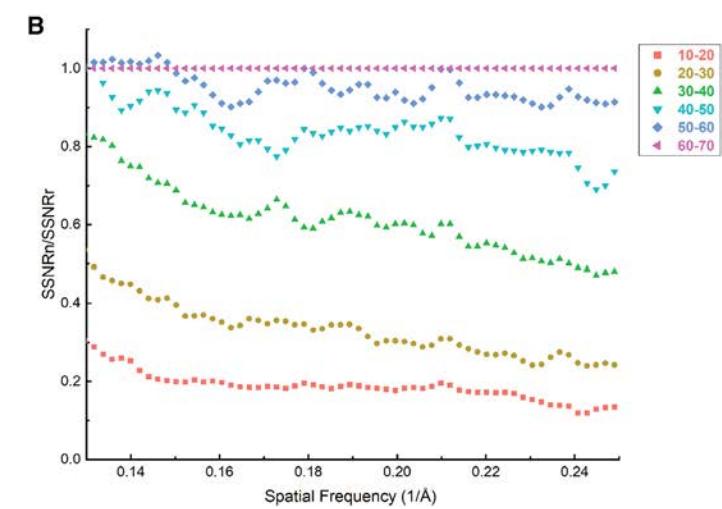
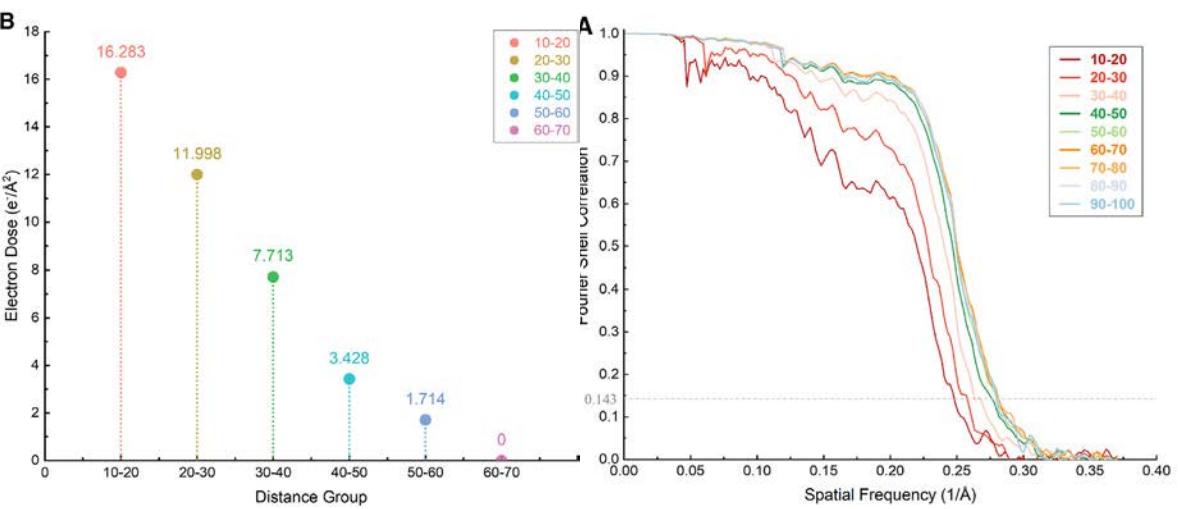
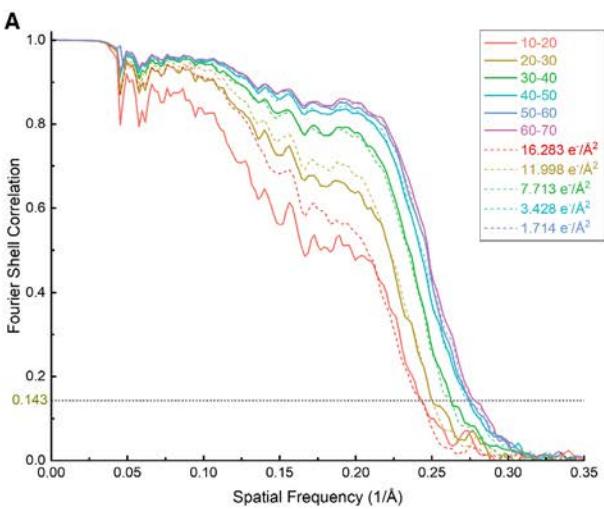
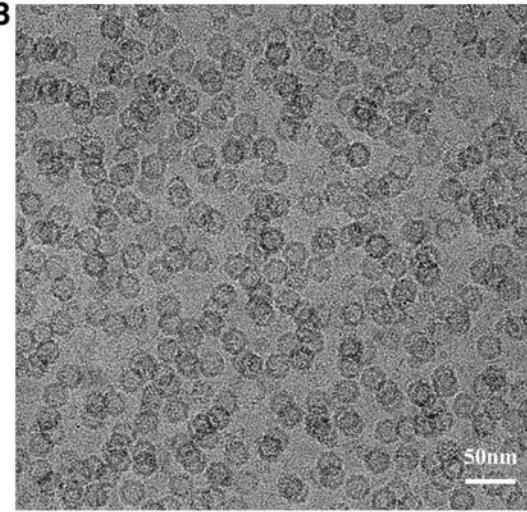
PFIB for cryo-lamella prep



cryo-lamella prep: damage

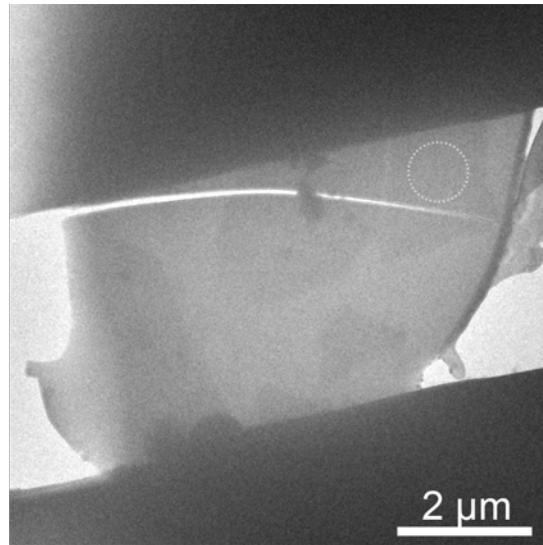


Cryo-lamella prep: damage

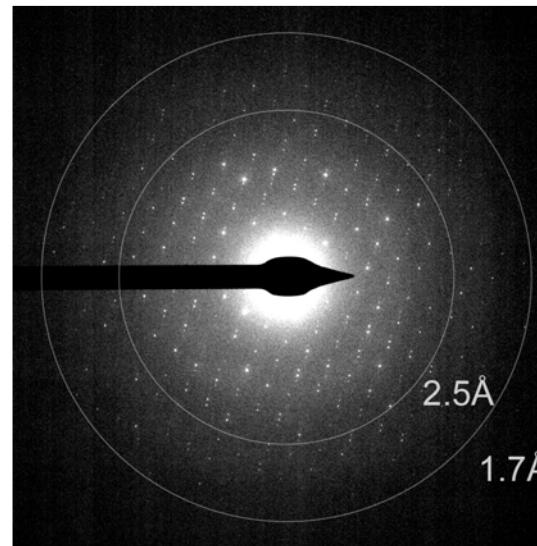
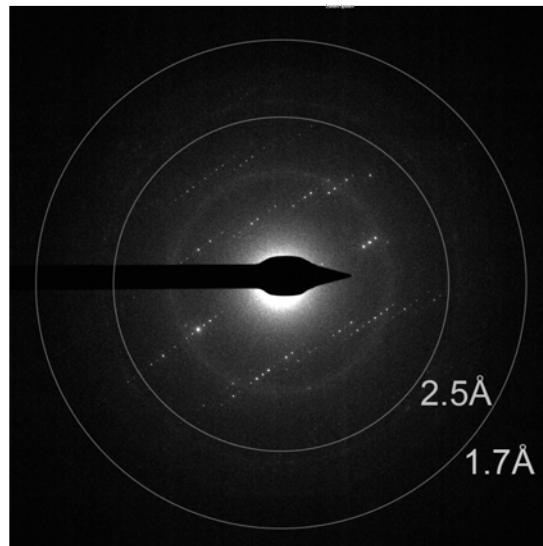
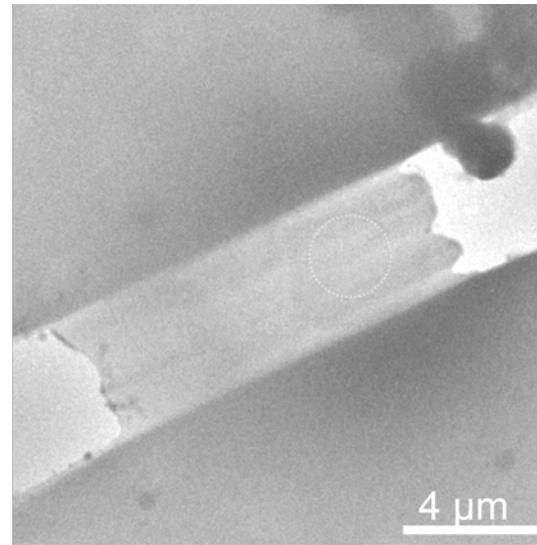
A**B**

PFIB for cryo-lamella prep

Gallium (8 min)

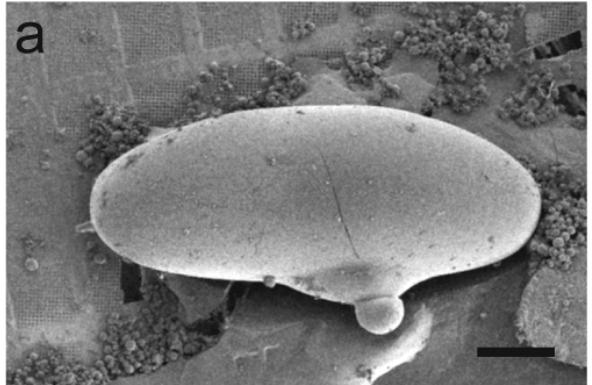


Argon (3 min)



PFIB for cryo–bulk removal

Ga



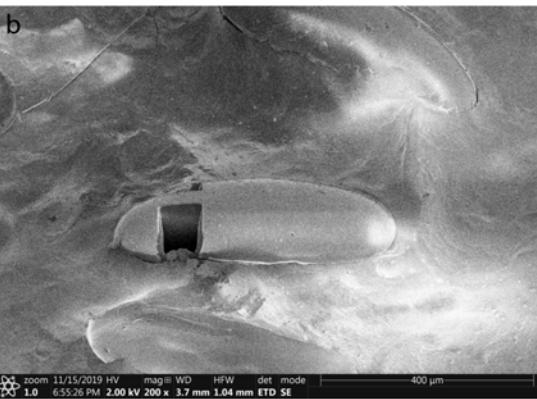
Heavy ions display increased re-deposition

Light ions display clean cut

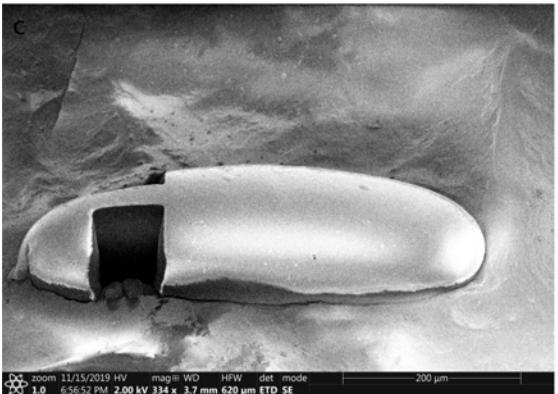
PFIB preparing cryo-lift out



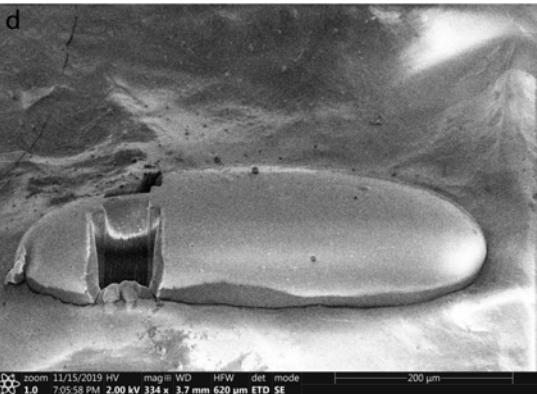
zoom 11/15/2019 HV
1.0 6:48:06 PM 2.00 kV 100



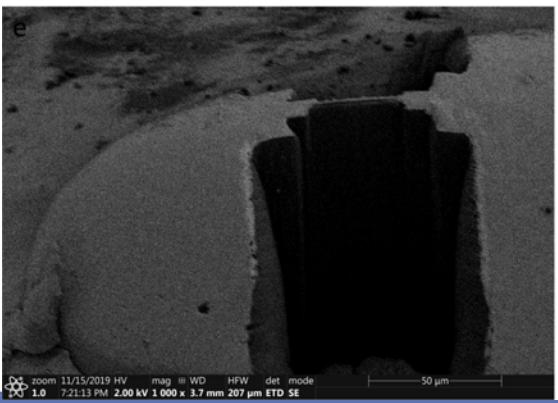
zoom 11/15/2019 HV mag WD HFW det mode 400 μm
1.0 6:55:26 PM 2.00 kV 200 x 3.7 mm 1.04 mm ETD SE



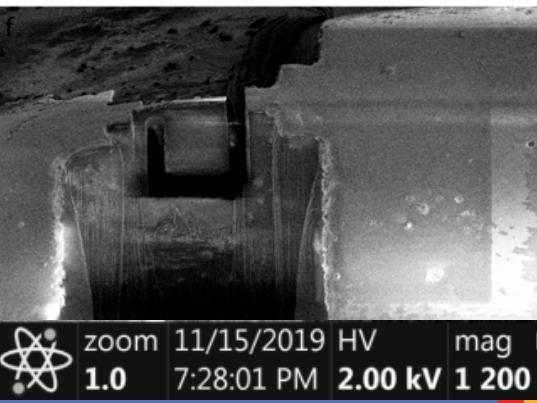
zoom 11/15/2019 HV mag WD HFW det mode 200 μm
1.0 6:56:52 PM 2.00 kV 334 x 3.7 mm 620 μm ETD SE



zoom 11/15/2019 HV mag WD HFW det mode 200 μm
1.0 7:05:58 PM 2.00 kV 334 x 3.7 mm 620 μm ETD SE

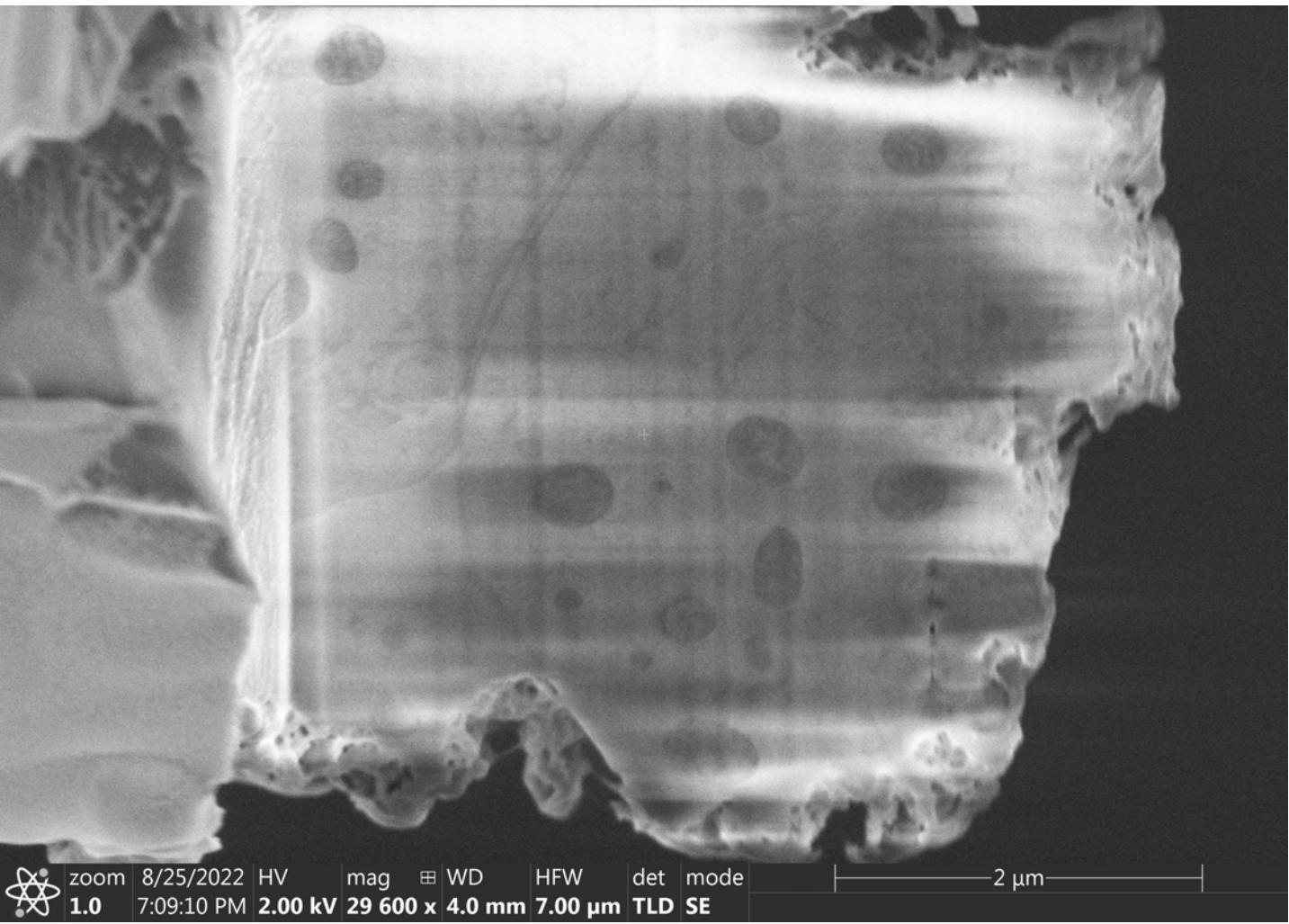
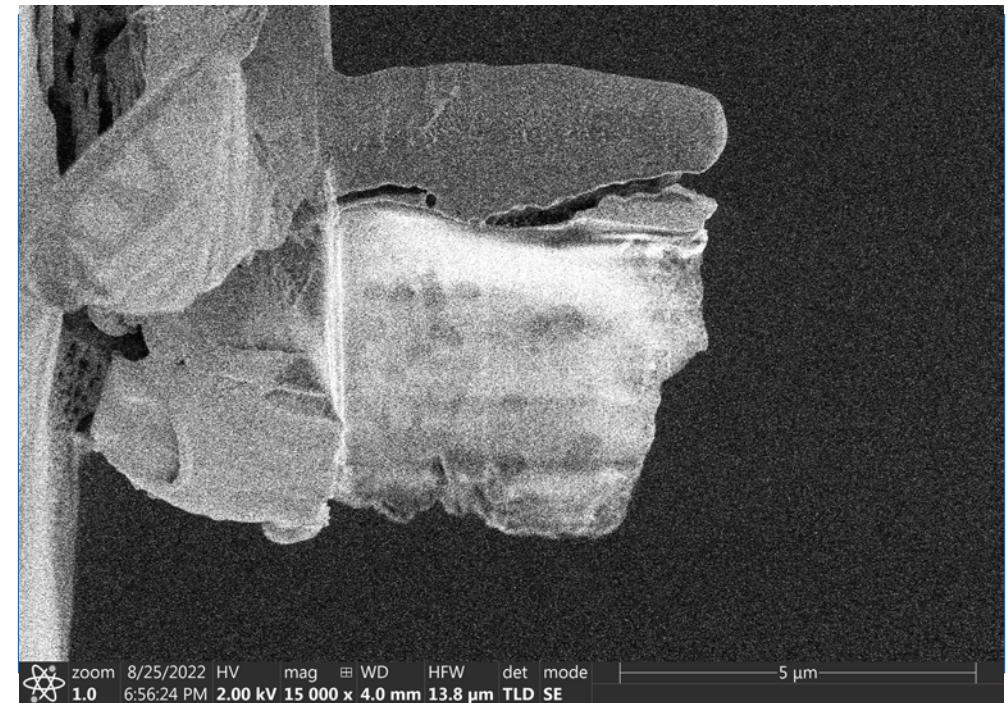


zoom 11/15/2019 HV mag WD HFW det mode 50 μm
1.0 7:21:13 PM 2.00 kV 1000 x 3.7 mm 207 μm ETD SE

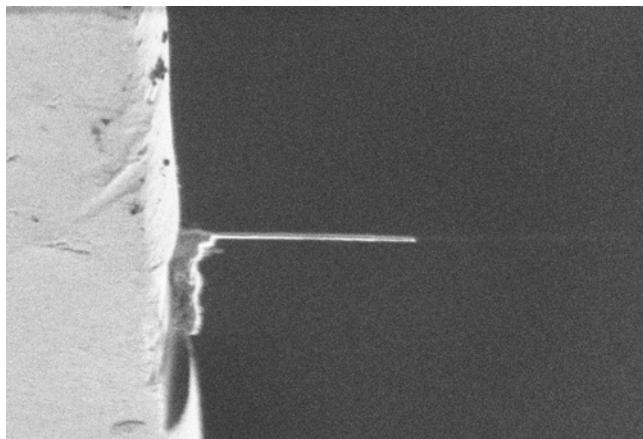
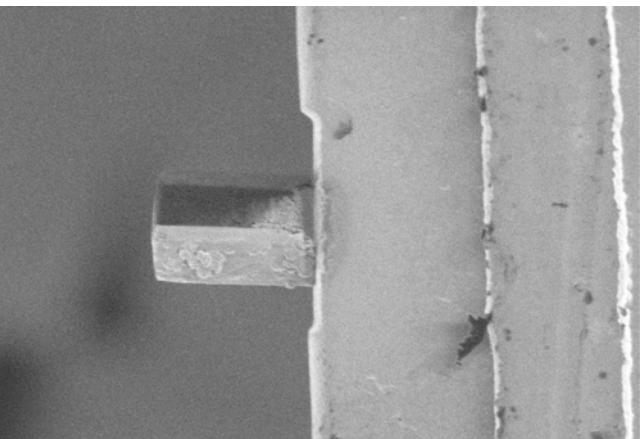
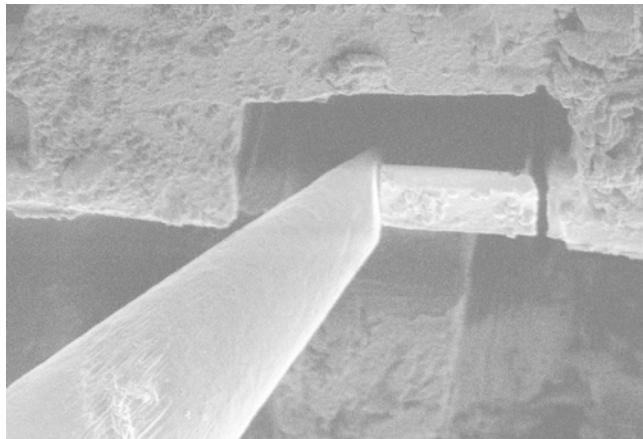
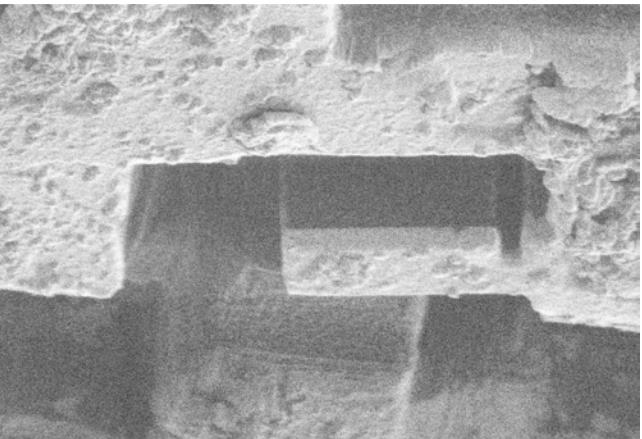


zoom 11/15/2019 HV mag
1.0 7:28:01 PM 2.00 kV 1 200

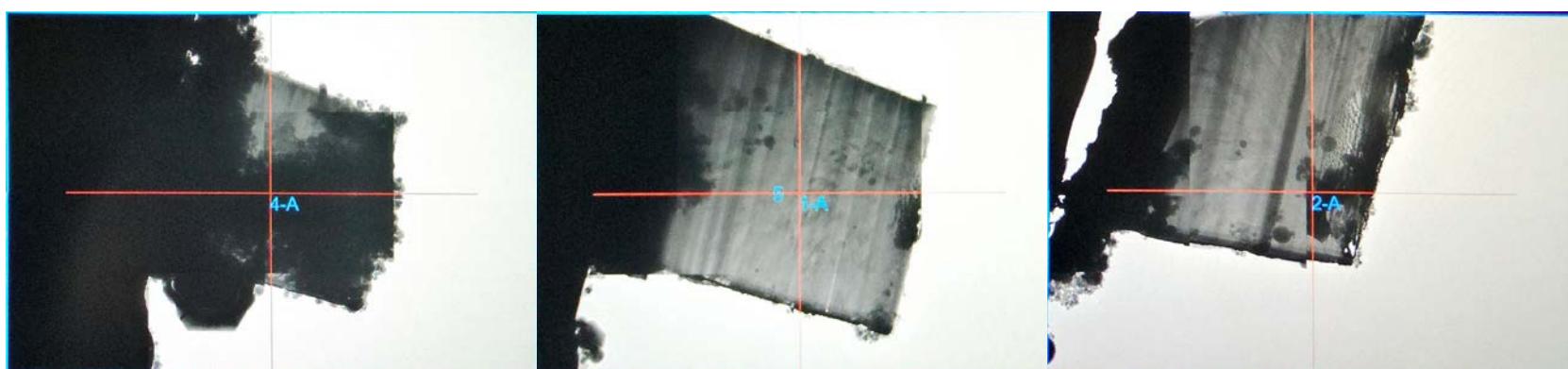
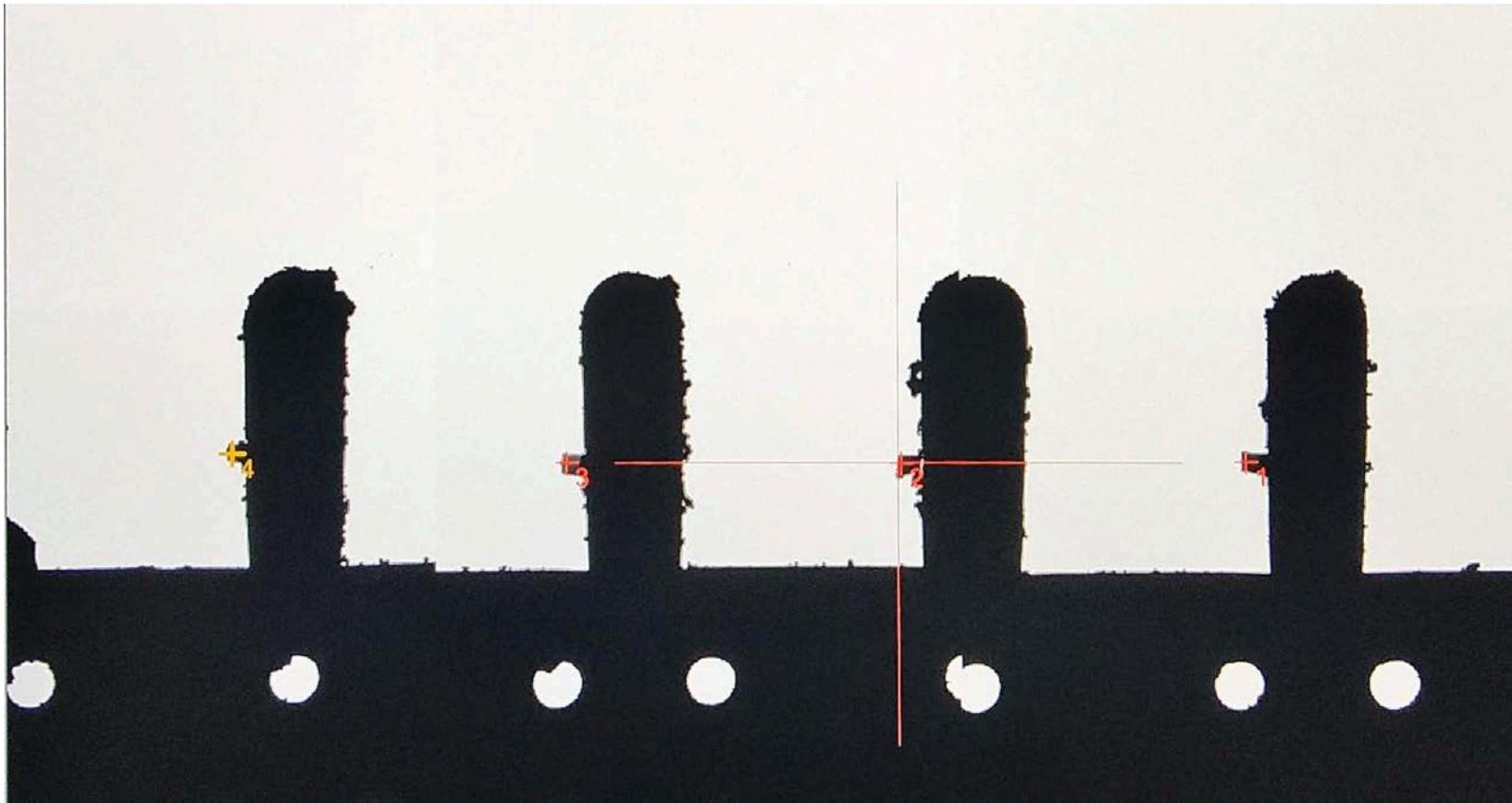
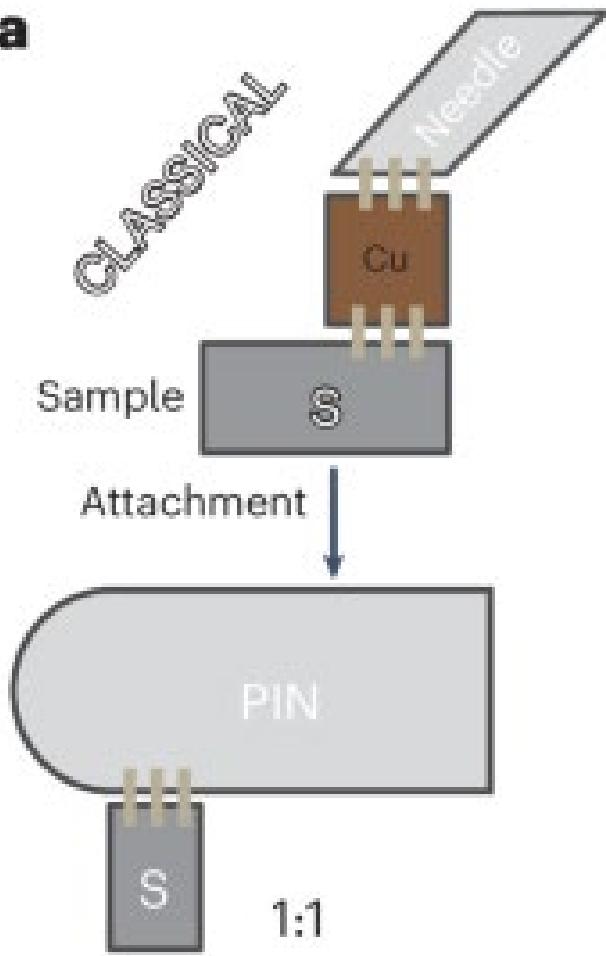
Liftout



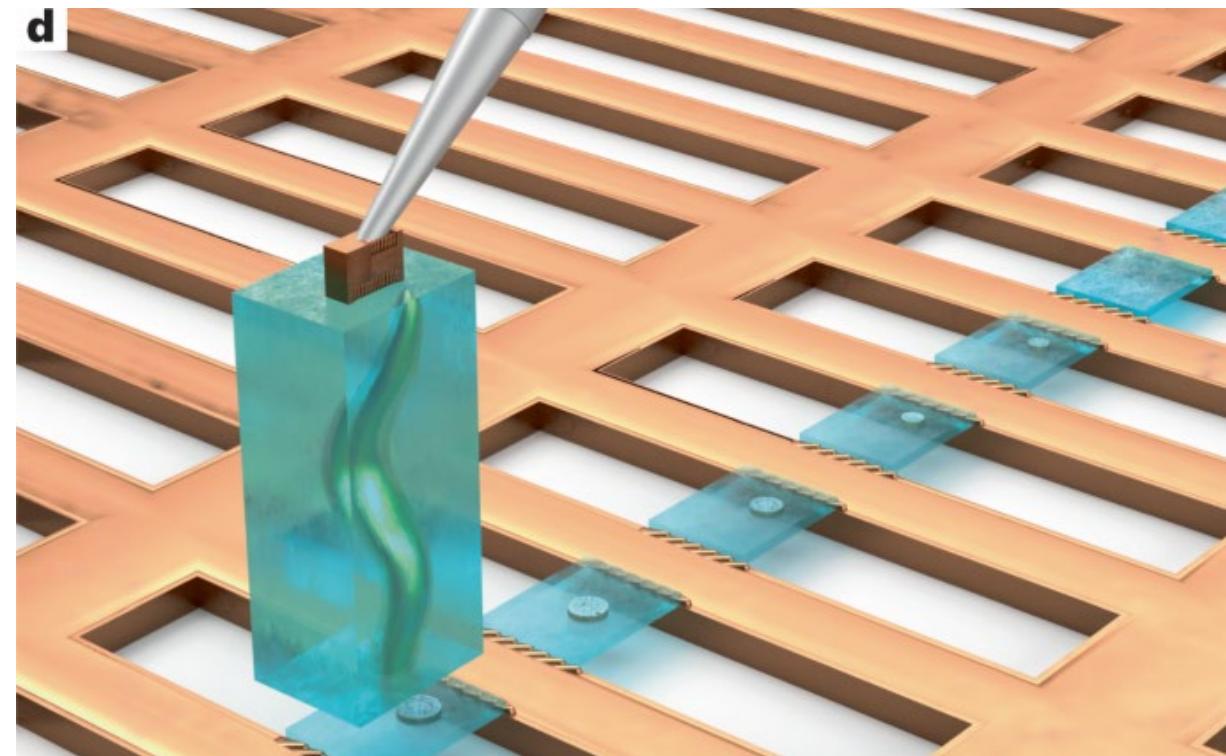
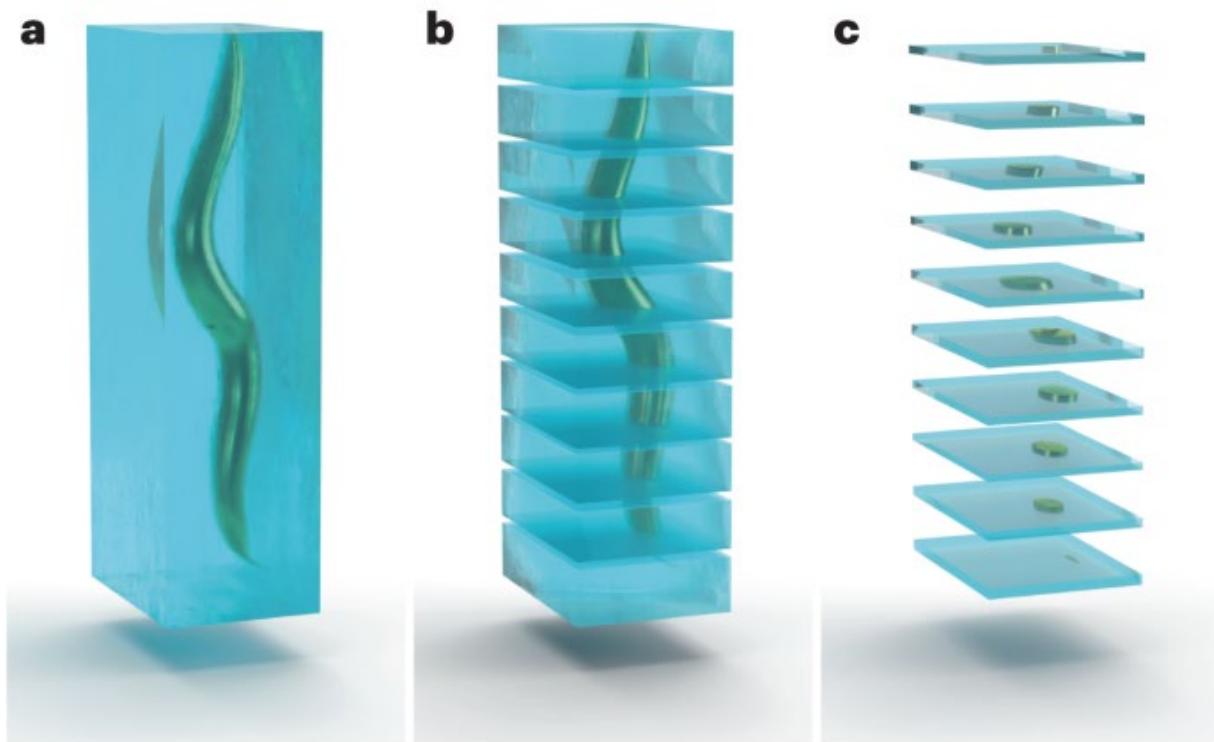
Liftout



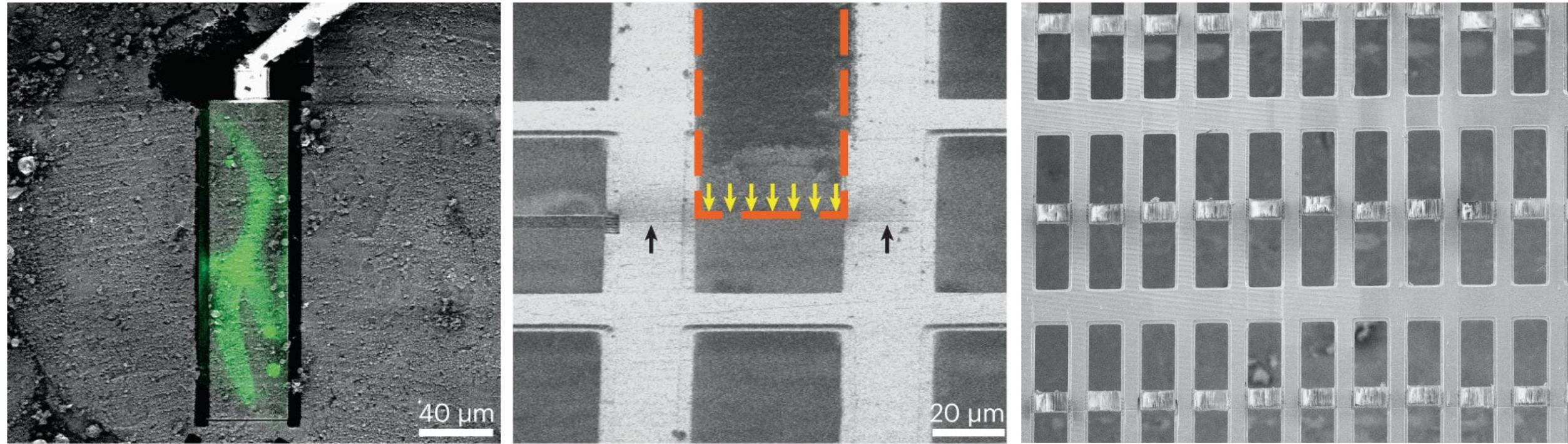
Liftout

a

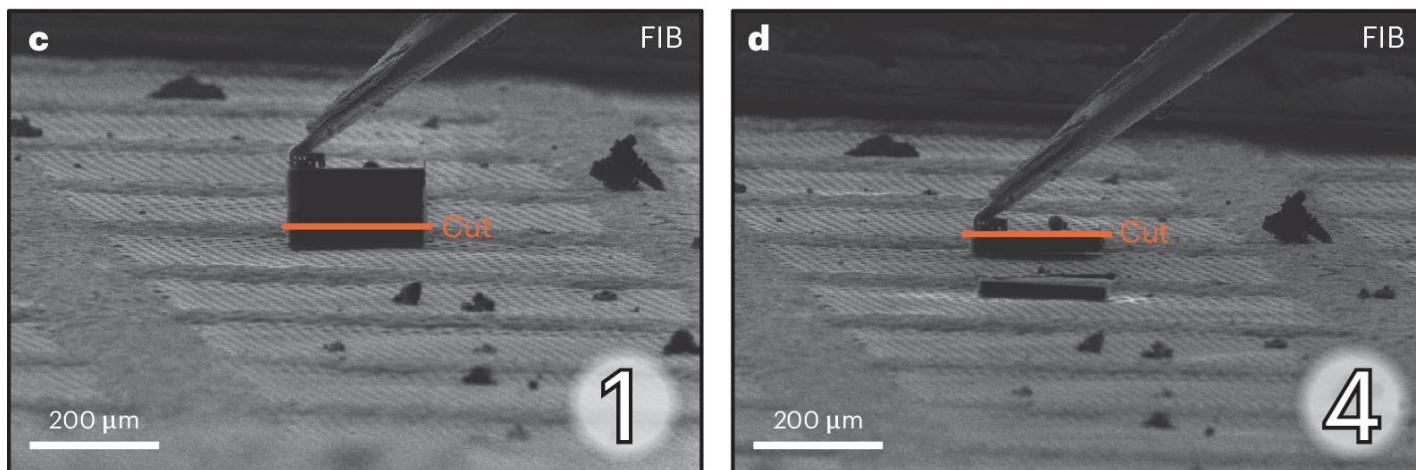
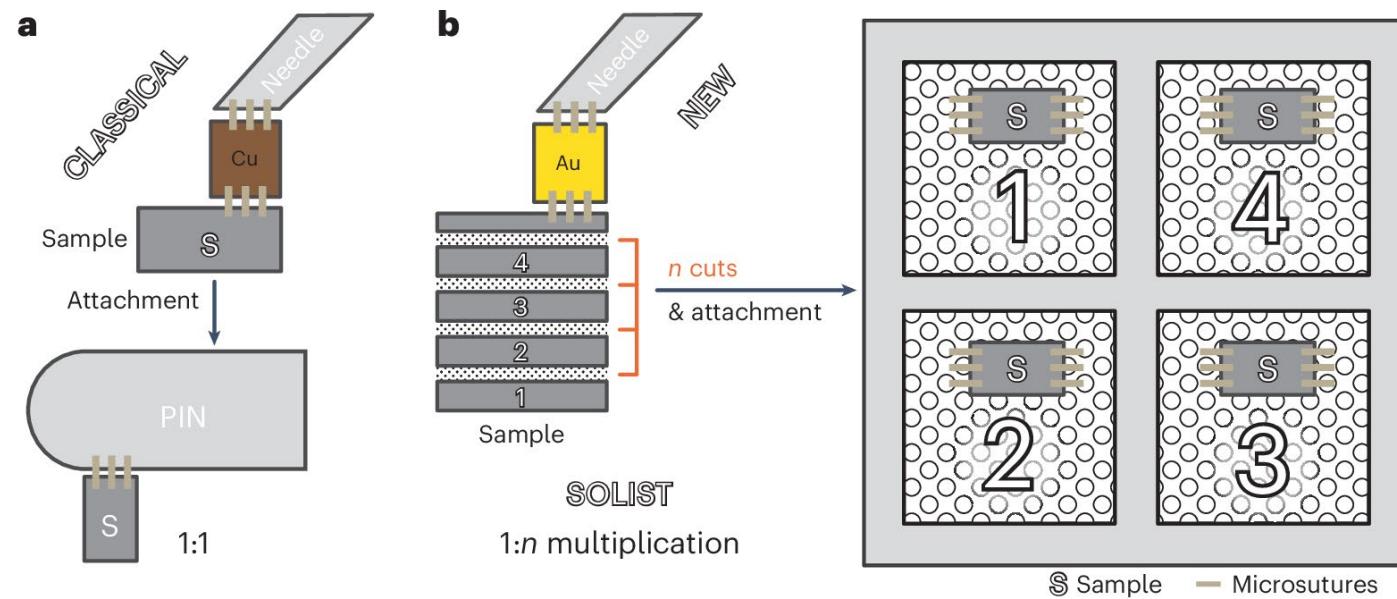
Serial Liftout



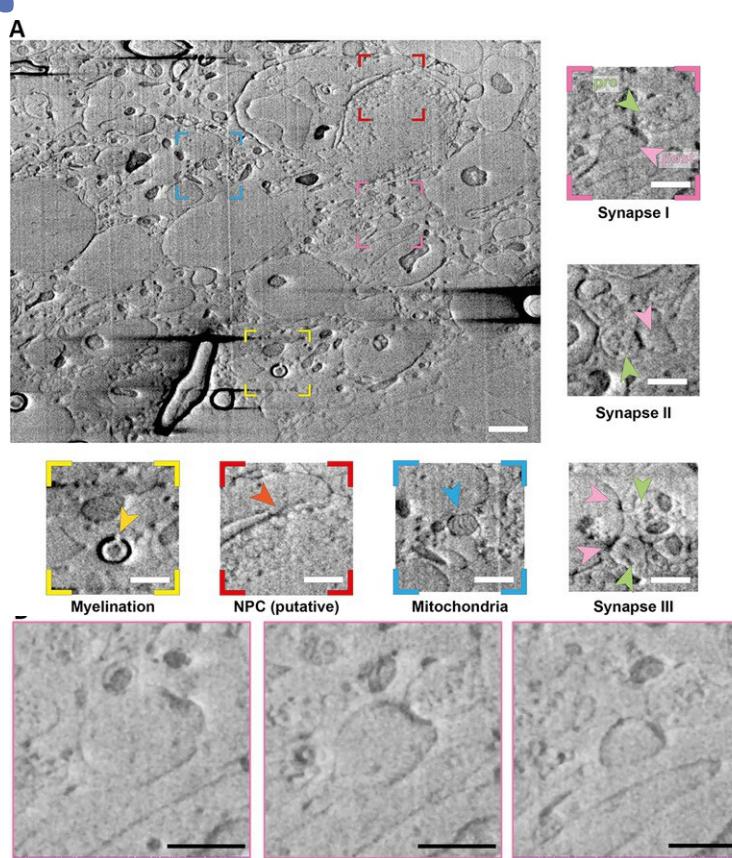
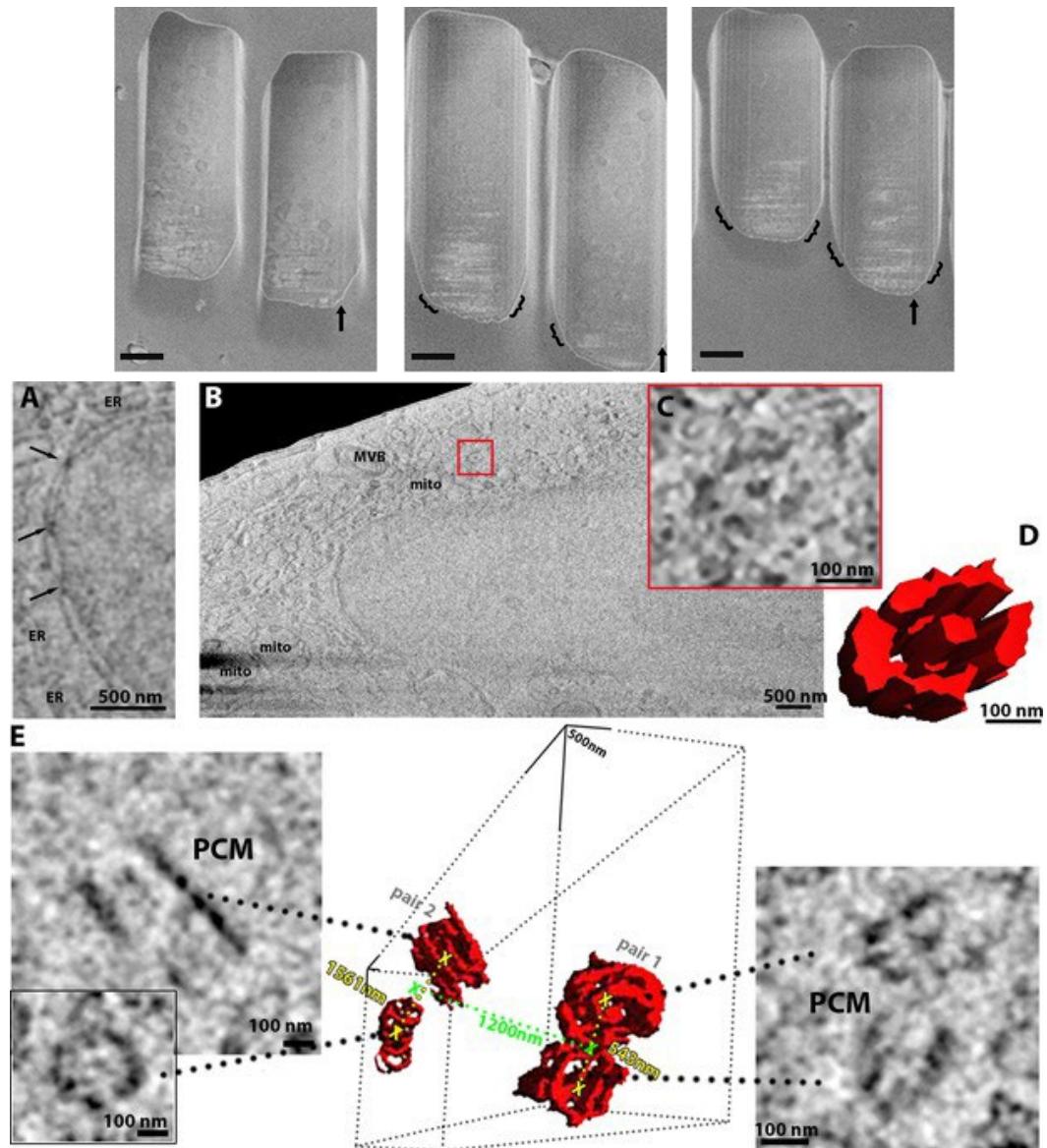
Serial Liftout



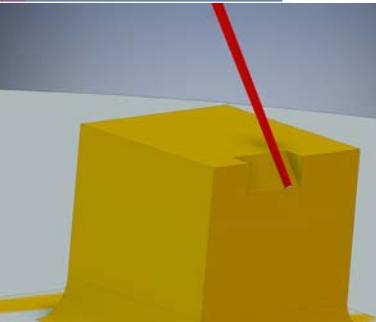
Serial liftout (SOLIST)

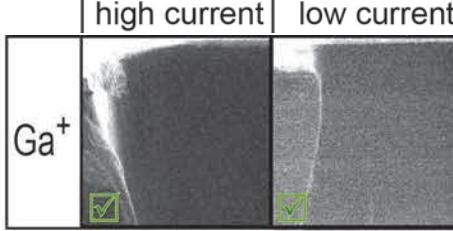
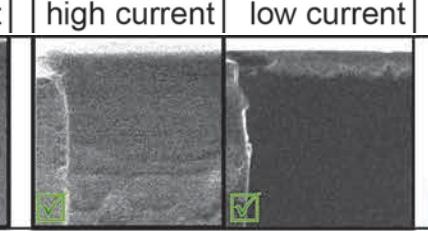
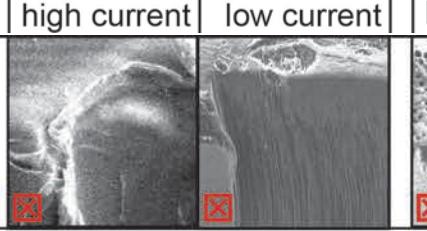
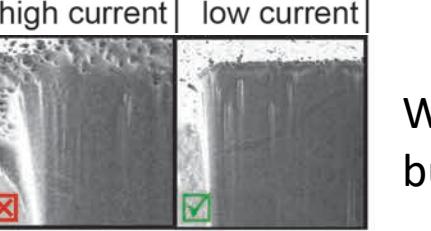
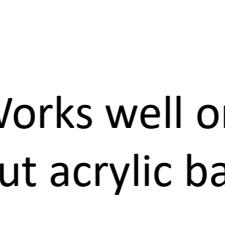
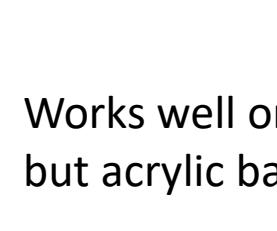
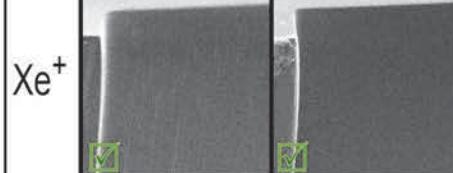
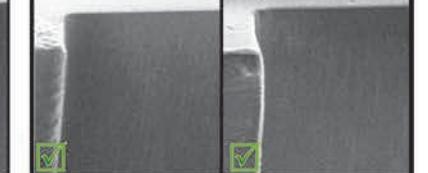
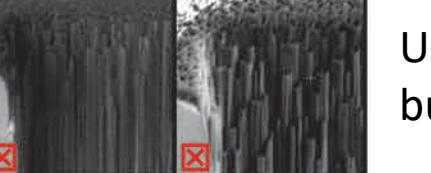
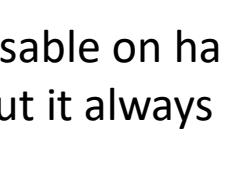
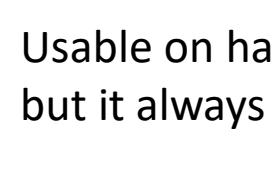
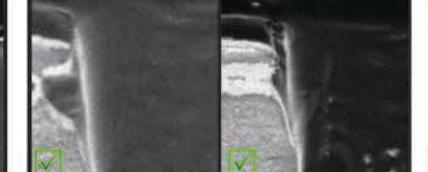
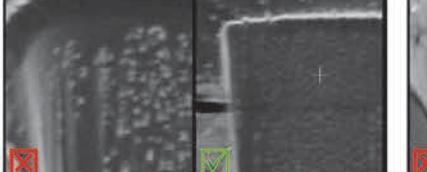
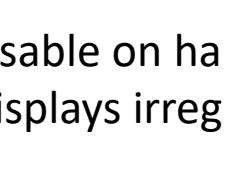
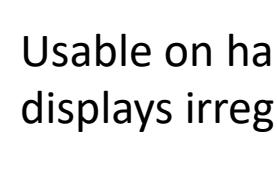
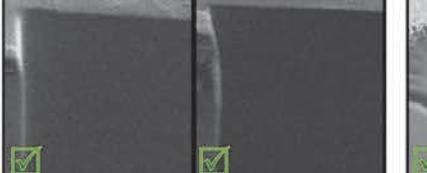
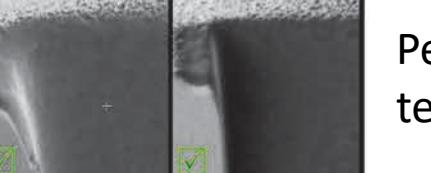
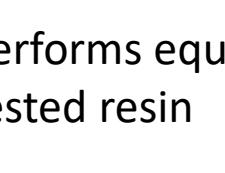
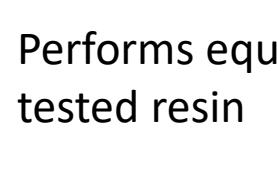


What if you need context?



Resin/ion beam compatibility



	Durcupan		Epon 812		HM20		LR-White	
	high current	low current	high current	low current	high current	low current	high current	low current
Ga ⁺								
Xe ⁺								
Ar ⁺								
O ⁺								

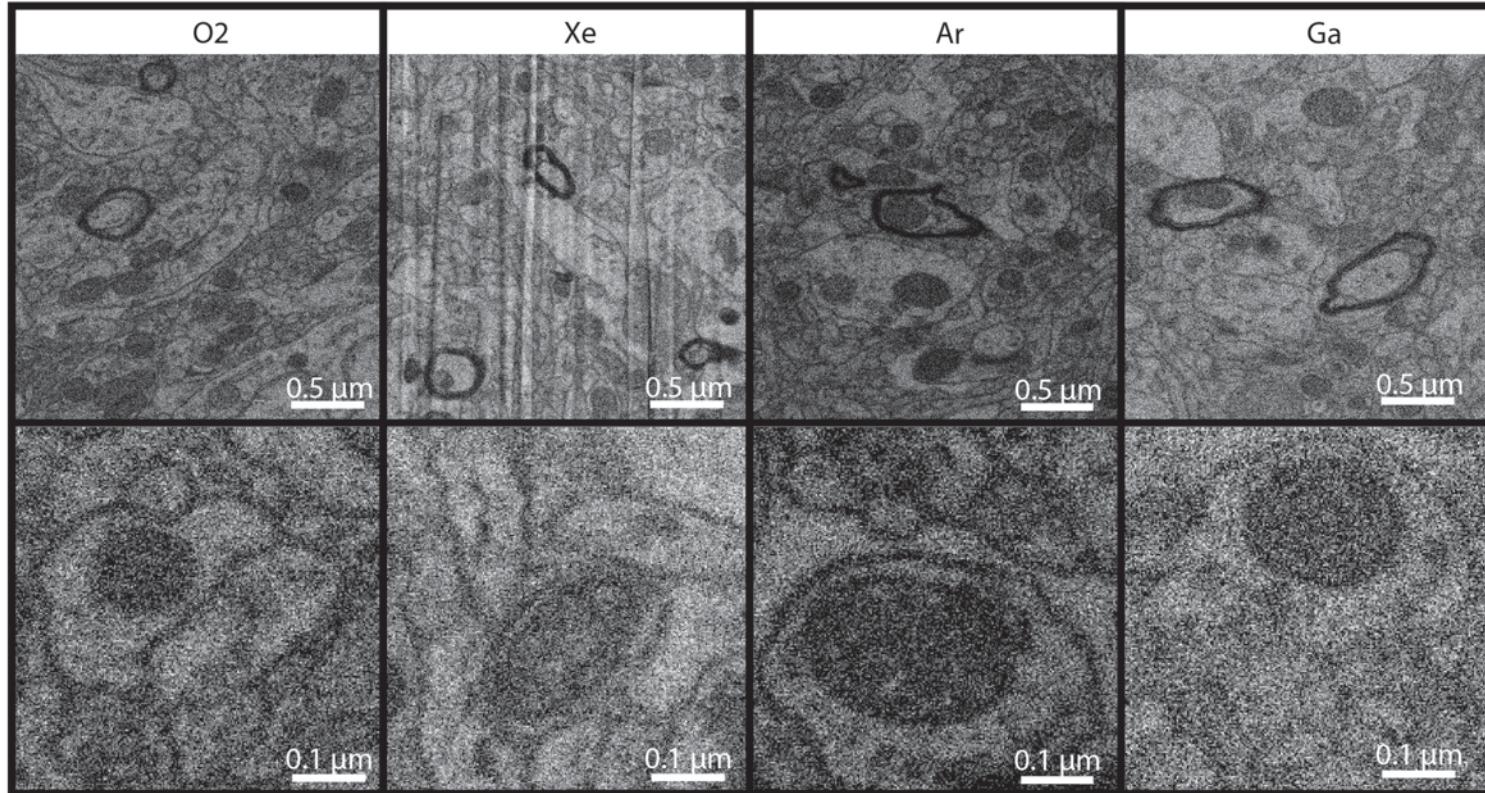
Works well on hard epoxy resins,
but acrylic based resins curtain or melt

Usable on hard epoxy resins,
but it always displays curtains

Usable on hard epoxy resins, but it
displays irregular milling efficiency

Performs equally on every
tested resin

Ga implantation reduces SNR when imaging



30% higher contrast when using non-metallic beams

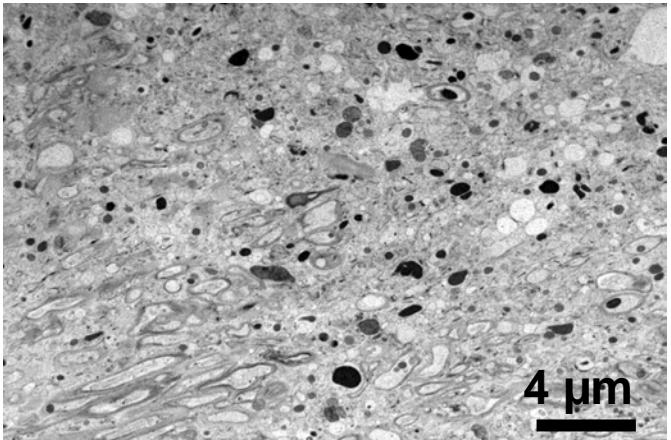


Faster imaging or better image quality

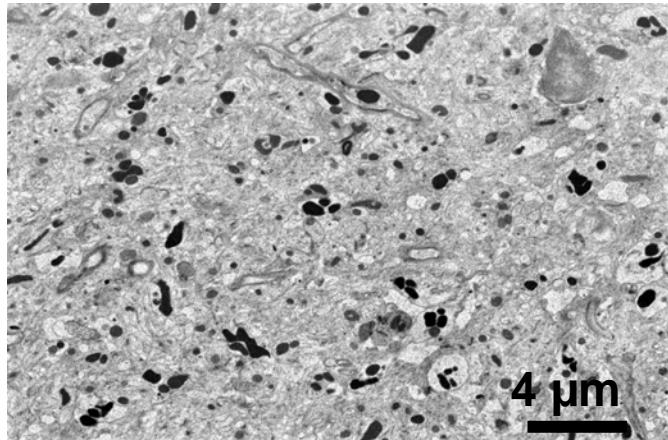
Mouse brain, embedded in epon

O₂ PFIB increases throughput on S&V

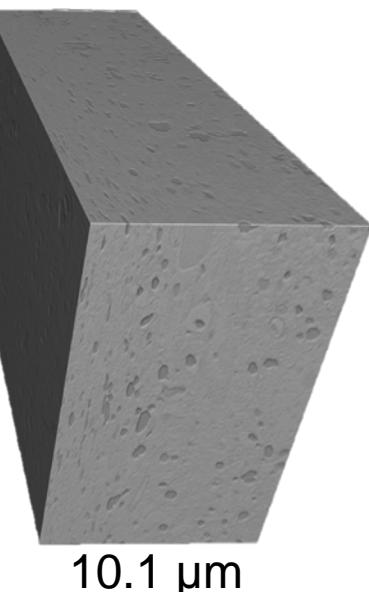
Mouse brain, embedded in epon acquired over 12h @5nm



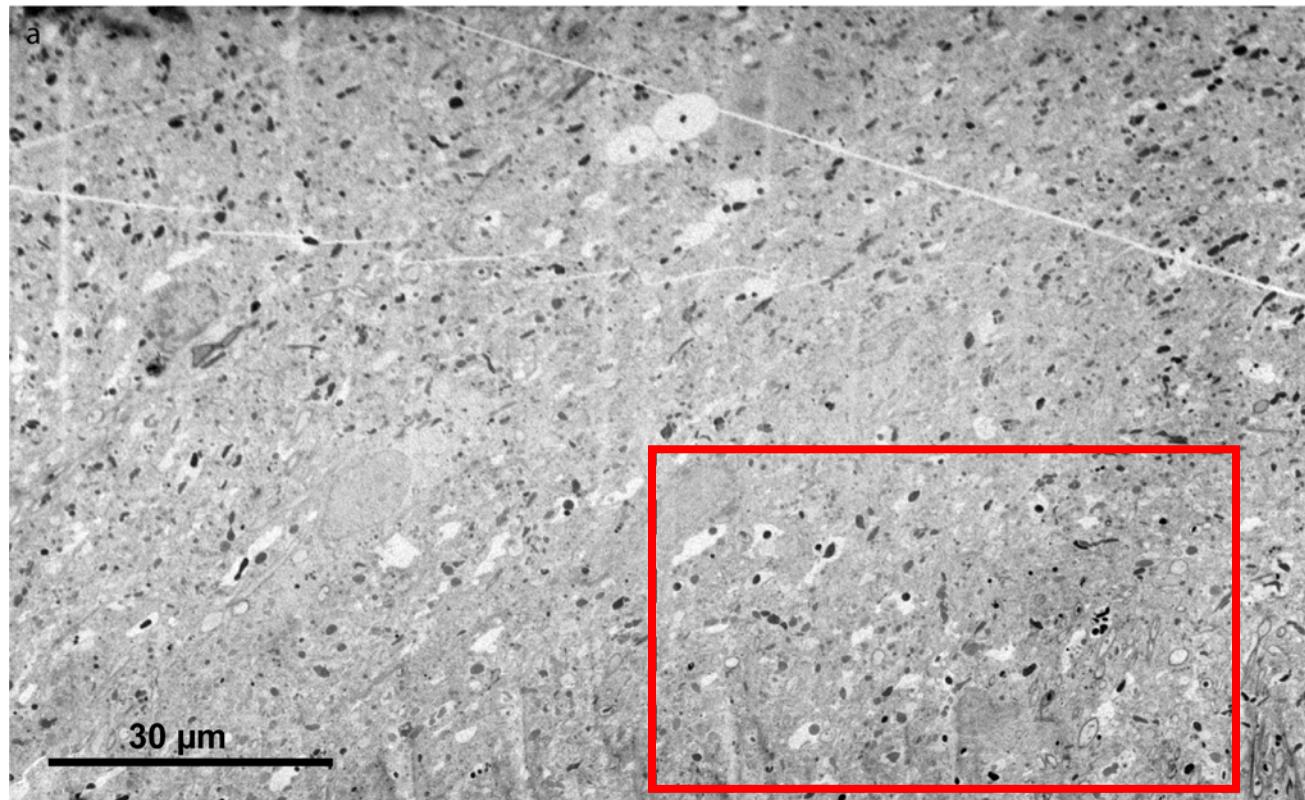
Ga



O₂

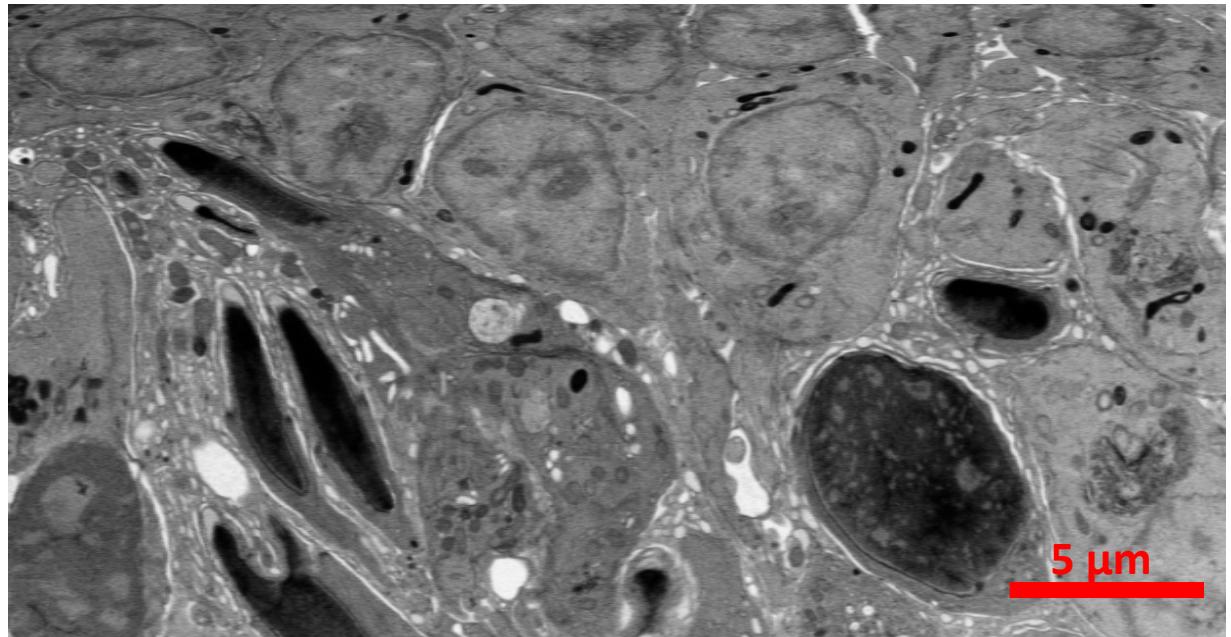
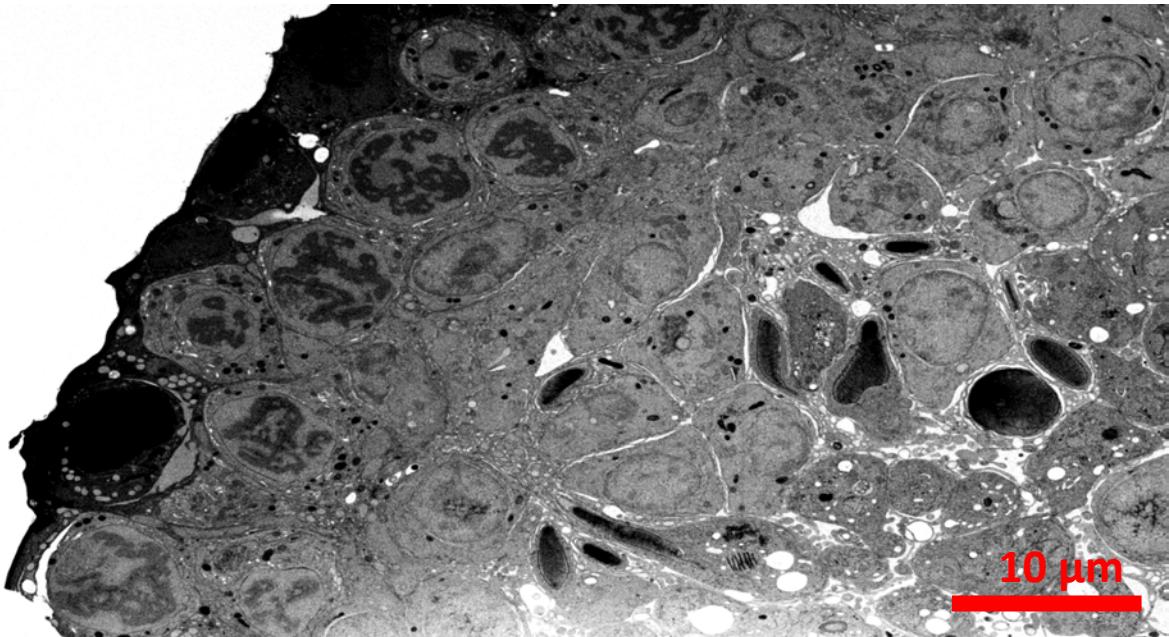


Large area on S&V (130x82 μm)



Increased throughput on S&V using O-PFIB

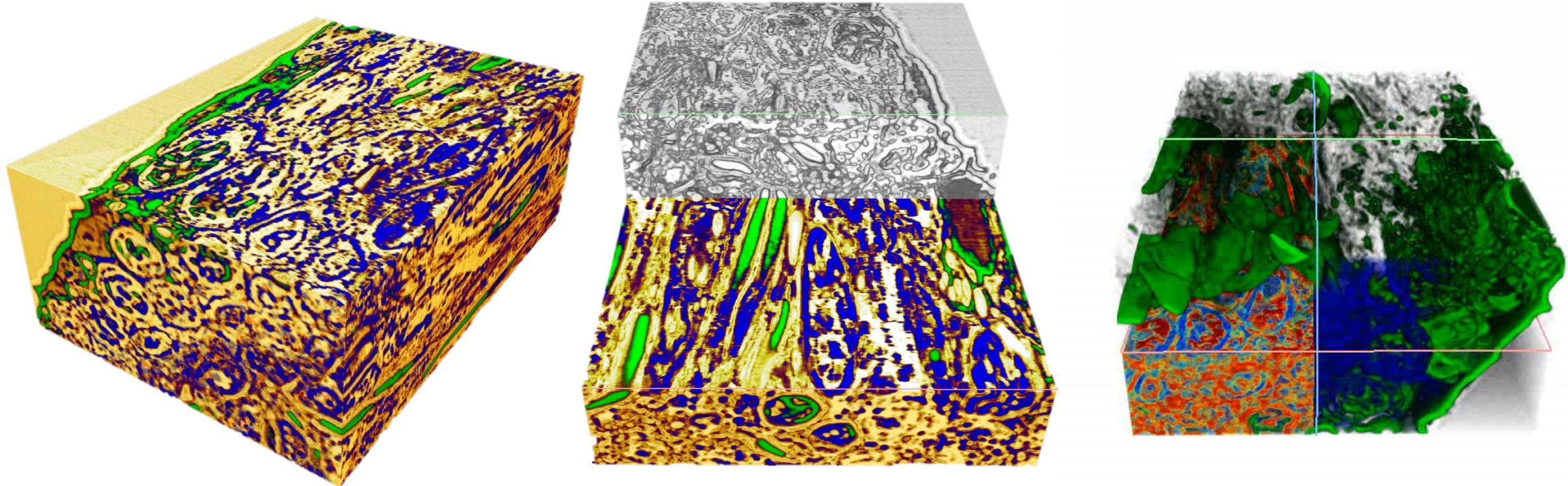
Mouse seminiferous tubule



2000 slices 6144*4096 pixel, voxel size 10*10*10 nm (61.44 * 40.96 um scan area). 45 nA oxygen ion beam. 2keV, 200pA electron beam 2 min per slice (milling + imaging)

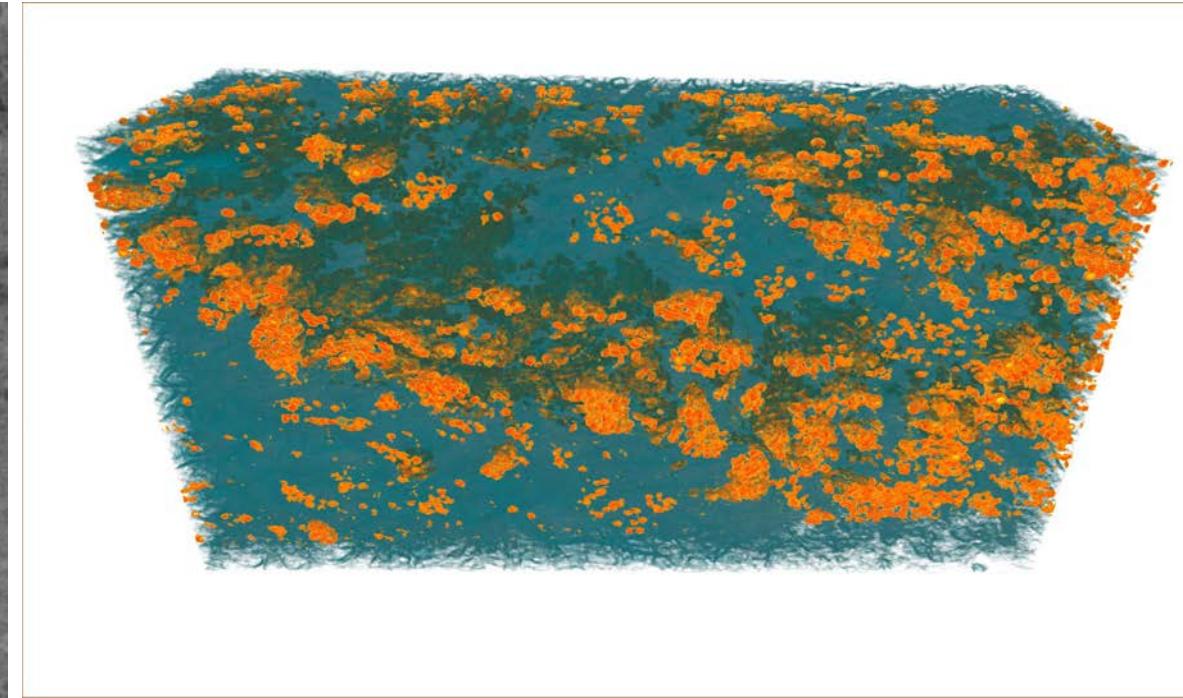
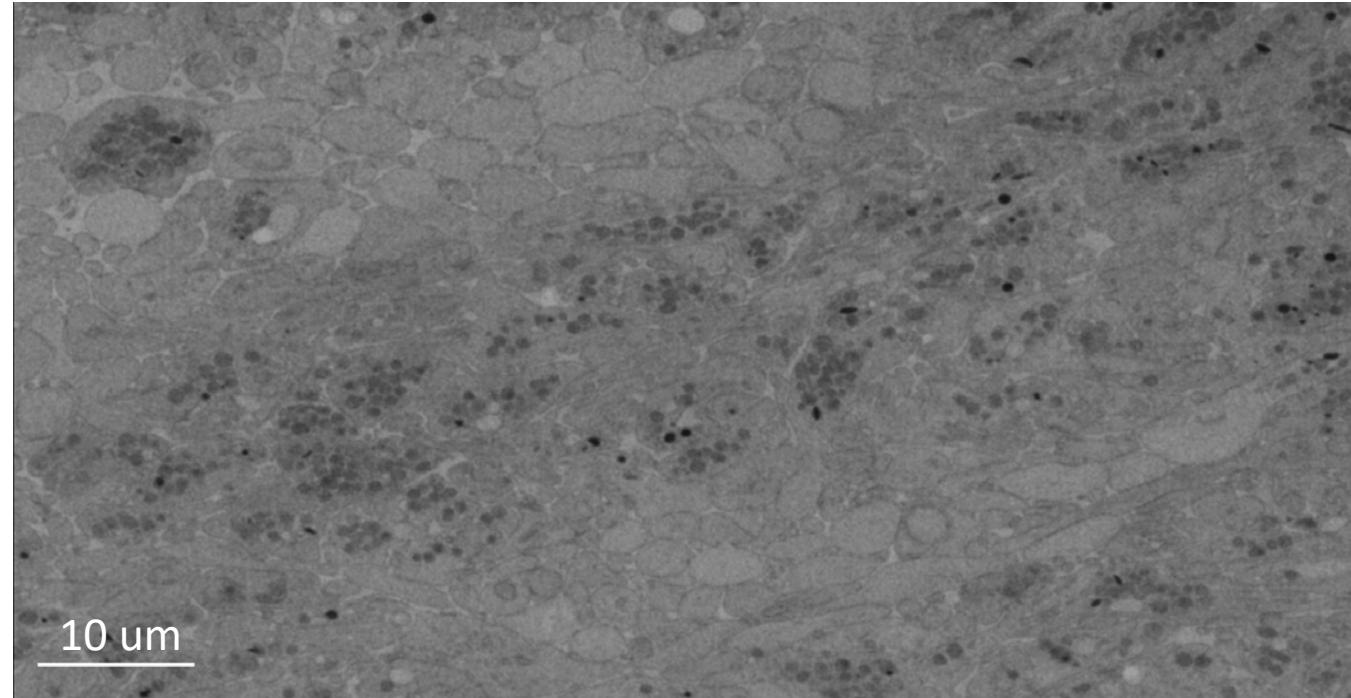
Increased throughput on S&V using O-PFIB

Mouse seminiferous tubule



2000 slices 6144*4096 pixel, voxel size 10*10*10 nm (61.44 * 40.96 um scan area). 45 nA oxygen ion beam. 2keV, 200pA electron beam 2 min per slice (milling + imaging)

Large volume FIB/SEM tomography



Blood clots imaged at 10 nm resolution
Trench size width is 100um
Imaged volume is 85x62x15 um over a weekend

Questions?